IEEE President Visit to Malaysia Section

IEEE President 2023, Prof Saifur Rahman visited the IEEE Malaysia Section from 22 Oct 2023 to 26 Oct 2023. Various programs were organized during the visits; Industry Engagement Programs, Meet the Leaders & Members, and Courtesy Visit to Malaysian Universities.

IEEE Day 2023 Malaysia Section

IEEE Day 2023 Malaysia Section was successfully organized on 14th October 2023 at the MMU Cinema, Faculty of Creative Multimedia, Multimedia University.
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Dear IEEE Malaysia Section members,

I am delighted to share with you the remarkable achievements and activities organized by our dedicated Organizational Units (OUs) during the final quarter of 2023. It is with immense pride that I report on the incredible contributions made by our members towards fostering innovation, knowledge exchange, and community engagement. Throughout October to December 2023, our OUs orchestrated a total of:

15 Meetings, Visits, and Social Activities - providing platforms for networking, collaboration, and camaraderie among our members.
25 Educational Activities - Empowering individuals with valuable skills and knowledge through workshops, seminars, and training sessions.
7 Awards and Recognitions - Acknowledging outstanding contributions and achievements within our IEEE community.
16 Professional and Industrial Relation Activities - Strengthening ties with industry partners and promoting professional development opportunities.
4 Membership Drives - Expanding our IEEE family and welcoming new members into our vibrant community.
51 Conferences and Talks - Facilitating discourse on cutting-edge research, trends, and advancements across various fields of interest.
9 Humanitarian Activities and Climate Change Initiatives - Demonstrating our commitment to societal welfare and environmental sustainability.

These accomplishments reflect the passion, dedication, and collaborative spirit of our members, volunteers, and leaders. I extend my heartfelt gratitude to each and every one of you for your unwavering commitment to advancing the mission of IEEE.

As we embark on a new year filled with fresh opportunities and challenges, let us continue to uphold the values of IEEE by promoting excellence, innovation, and service to humanity. Thank you for your continued support, and I look forward to another year of fruitful collaboration and success.

Best regards,

Mohd Hafiz Ismail
Newsletter Editor 2023-2024
IEEE Malaysia Section
Dear Esteemed Members of IEEE Malaysia Section,

As we approach the culmination of 2023, I am thrilled to share the exciting developments that have characterized our collective journey during this fourth quarter. Throughout the past few months, our commitment to fostering a dynamic and connected community has materialized through a diverse array of successfully executed events, both physical and virtual. Noteworthy among them were the insightful visits to factories in Penang and other places, offering our members invaluable exposure to the cutting-edge technologies shaping our industry.

A standout moment was the successful visit of Prof Saifur Rahman, the esteemed IEEE President, to Malaysia. This not only served as a testament to our dedication to engaging with stakeholders at the highest echelons but also underscored the pivotal role played by the IEEE Malaysia Section in the global technological landscape, contributing significantly to advancements for the betterment of humanity. Furthermore, we actively participated in crucial discussions with various stakeholders, addressing pressing issues such as climate change and renewable energy. These dialogues are instrumental in guiding our approach toward sustainable and responsible technological advancements.

As we stand at the threshold of a new year, let us envision the forthcoming months as a canvas of possibilities, ripe for breakthroughs and shared achievements. Together, let us continue building bridges of understanding, inspiring one another, and collectively shaping a future that mirrors the brilliance of our shared commitment to advancing technology for the benefit of humanity. In the spirit of collaboration, I urge each of you to embrace 2024 as a year where innovation knows no bounds. Let our collective efforts propel us to new heights, shaping the technological landscape and making a positive impact on society.

The IEEE Malaysia Section is honored to be home to a community of dedicated individuals, and we eagerly anticipate another year of making impactful contributions to the world of technology. My heartfelt gratitude goes out to you for your unwavering support, passion, and commitment. Thank you for being an integral part of the IEEE Malaysia Section’s journey. Here's to a remarkable 2024 filled with endless possibilities.

Best Regards,

Nordin Ramli
Chair, IEEE Malaysia Section
IEEE President 2023, Prof Saifur Rahman paid IEEE Malaysia Section a visit from 22 Oct 2023 till 26 Oct 2023. The IEEE President visit to Malaysia was hosted by IEEE Malaysia Section and its chapter. Various programs were organized during the visits.

1. Industry Engagement Programs
2. IEEE President Meet the Members
3. IEEE President courtesy visit to Malaysian Universities

The Industry Engagement Programs is organized between the IEEE R10 Ad hoc Industry Round Table on climate change with IEEE Malaysia Section. This industry engagement program were organized with a seminar to get all relevant parties in the industry involve in Climate Change to come together to discuss on it and then follow up by a round table discussion. The event was on 25 Oct 2023, 8.30AM – 4.00PM held at UNITEN, Kuala Lumpur, Malaysia. The event were organized into two sessions. In the morning session a Seminar: Utilizing Technology to Combat Climate Change while the afternoon session an Industry Engagement through Round table discussion between Industry, Academia, Government/Regulatory and IEEE. People in this session are, Schneider Electric, GSparx, University Malaya, UNITEN, UTAR, UiTM, TNB, TNB Research, Energy Commission, Consultant.
IEEE President Visit to IEEE Malaysia Section

Reported by: Bernard Lim
(IEEE Malaysia Section Chair-Elect, berna_rd@ieee.org)

Industry Engagement through Round table discussion

As part of the Ad hoc Round Table on Climate Change, an Industry Engagement through Round table discussion between Industry, Academia, Government/Regulatory and IEEE. People in this session are, Industry (Schneider Electric, Gsparx, TNB, TNB Research, Consultant), Academia (University Malaya, UNITEN, UTAR, UiTM), Government (Energy Commission) were been conducted.

IEEE President Meet the Members were organized through SYWL Initiatives

During the IEEE President, Prof Saifur Rahman visit to Malaysia, there were a few events schedule for the members/ leaders/ excom to meet up with the President.

Program1: IEEE Malaysia Section SYWL Meet up with the President
Date: 24 Oct 2023
Venue: Asia Pacific University, Technology & Innovation, KL
Number of pax: 100+

The IEEE President provided lecture relating to climate change to the IEEE Members.
IEEE President Visit to IEEE Malaysia Section

Reported by: Bernard Lim  
(IEEE Malaysia Section Chair-Elect, berna_rd@ieee.org)

IEEE President Meet the Members were organized through SYWL Initiatives (con’t)

IEEE President Meet the Leaders

Program 2: IEEE President Meet the leaders (IEEE Malaysia Section Excomm, chapter chairs, AG, WIE, Sub-section)  
Date: 24 Oct 2023  
Venue: University Malaya, KL (Hybrid)  
Number of pax: 25

IEEE Members Meet's the IEEE President, Prof Saifur Rahman

IEEE President Meet the leaders (IEEE Malaysia Section Excomm, chapter chairs, AG, WIE, Sub-section)
IEEE President Visit to IEEE Malaysia Section

Reported by: Bernard Lim
(IEEE Malaysia Section Chair-Elect, berna_rd@ieee.org)

IEEE President Courtesy visit to Malaysian Universities

During the IEEE President, Prof Saifur Rahman visited some of the Malaysian Universities. There were three universities.

1. Courtesy visit to Universiti Tunku Abdul Rahman (UTAR), KL
   Date: 23 Oct 2023
   Time: 9.00 AM – 11.30 AM
   Venue: Universiti Tunku Abdul Rahman Sungai Long Campus

2. Courtesy visit to Universiti Malaya, KL
   Date: 24 Oct 2023
   Time: 11.30 AM – 1.30PM
   Venue: Universiti Malaya, Kuala Lumpur, Malaysia

3. Courtesy visit to Asia Pacific University of Technology & Innovation, KL
   Date: 24 Oct 2023
   Time: 5.00 PM – 6.30PM
   Venue: Asia Pacific University of Technology & Innovation, Kuala Lumpur, Malaysia

IEEE President, Prof Saifur Rahman shared to UTAR management on IEEE initiaves on Climate Change.

IEEE President Courtesy visit to UTAR

Group Photo with the IEEE President, Prof Saifur Rahman and President of UTAR, Ir. Professor Dato' Dr. Ewe Hong Tat
IEEE President Visit to IEEE Malaysia Section

Reported by: Bernard Lim
(IEEE Malaysia Section Chair-Elect, berna_rd@ieee.org)

IEEE President Courtesy visit to UM

IEEE President Courtesy visit to APU
Eight members from the IEEE Malaysia Section have been appointed as the IEEE Day Core Team and IEEE Day Ambassadors for the IEEE Day 2023:

**IEEE Day Core Team (Communication Lead)** Mohd Hafiz Ismail

**IEEE Day Ambassadors Malaysia Section:**
- Alina Aslam
- Aslina Baharum
- Intan Fatimah Sasila Ghadzali
- Mohd Haizal Jamaluddin
- Muzaidi Othman
- Nurul Afiqah Syazana Mohd Jafri
- Sibly Noman

**IEEE Day 2023 events by the IEEE Malaysia Section**

- **09 Oct 2023** IEEE Malaysia Section Women in Engineering Capacity Building and Skill Enhancement Competition (IEEE Malaysia Section Women in Engineering Affinity Group)
- **14 Oct 2023** IEEE Day 2023 Malaysia Section (IEEE Malaysia Section)
- **14 & 24 Oct 2023 & 4 Nov 2023** Young Professionals Malaysia Meet-Up @ IEEE Day 2023 (IEEE Malaysia Section Young Professionals Affinity Group)
- **14 Oct 2023** LMAG Technical Talk: Sky-High Solutions - Can AI and UAVs Transform Malaysia’s Palm Oil Industry? (IEEE Malaysia Section Life Member Affinity Group)
- **14 Oct 2023** Integrating Sustainable Energy and Smart Agriculture: Empowering Communities and Promoting Environmental Sustainability (IEEE Malaysia Section)
Professional Activities & Industry Relations

Reported by: Nabilah Ibrahim
(IEEE Malaysia Section Executive Committee, nabilah@uthm.edu.my)

IEEE Malaysia Section on Professional Activities and Industrial Relations in collaboration with IEEE Malaysia Section Electronics Packaging Society (EPS) has successfully organized a physical workshop on Advanced Packaging webinar on 19 September 2023 attended by almost 50 participants. The workshop was broken up into two topics:

a) Material and Process Trends in Fan-out WLP and PLS - 17 October 2023
b) Exploring Chiplets and the New Era of Advanced Packaging - 19 October 2023

On 17 October 2023, the speaker was Dr. Tanja Braun who is the group manager Fraunhofer IZM Berlin, Germany. Meanwhile, on 19 October 2023, E. Jan Vardaman, the President and Founder of TechSearch International, has led the workshop. A lot of good questions were raised relating to the type of analytical solution to address problems faced.

IEEE Malaysia Section on Professional Activities and Industrial Relations in collaboration with IEEE Malaysia Section Electronics Packaging Society (EPS) has successfully conducted the below onsite technical visits. Both visits participated by 25 members and non-members, aimed to provide a platform for networking for IEEE members and an avenue for technical discussion:

i) Indium Corporation at Bandar Cassia, Batu Kawan, Penang on the topic of Solder Paste Manufacturing Process. The visit was held on 18 August 2023.

ii) NXP Malaysia Sdn Bhd at Sungai Way Trade Industrial Zone on Advanced Packaging. It was held on 10 October 2023.

IEEE Malaysia Section on Professional Activities and Industrial Relations in collaboration with IEEE Malaysia Section ComSoc/VTS Joint Chapter Malaysian has successfully organized a webinar on 19 September 2023, delivered by Prof. Dr. Huseyin Arslan who is the IEEE Fellow from Istanbul Medipol University. The webinar was participated by nearly 60 IEEE members and non-members that came from the industry as well as academia. The topic focused on fellowship in IEEE and also the research opportunity with Turkey on the 6G ecosystem. The webinar has increased opportunity to industries and academicians in Malaysia and Turkey to engage research collaboration in 6G networks and technology.
The IEEE Malaysia Section Humanitarian Activities Committee has been awarded a grant of USD 400 from the IEEE R10 Humanitarian Sustainable Project & Volunteer Training Support Fund-2023. This grant has facilitated a knowledge-sharing session centered on a groundbreaking humanitarian project that addresses challenges related to rural energy and smart hydroponics to enhance living conditions and promote sustainability. The event, took place at Multimedia University, Cyberjaya.

Topics included solar system installations for remote regions and the use of smart hydroponic systems in densely populated flats, highlighting advantages, obstacles, and potential collaborative opportunities. This knowledge-sharing session directly addresses community needs, advocating for sustainable development through technology and positioning the IEEE Malaysia Section as proactive and knowledgeable. The event aims to raise awareness, inspire action, and foster collaborations, contributing to positive change for a more sustainable future.

The synergy between sustainable energy and smart agriculture creates a harmonious ecosystem for agricultural development. This integration marks a pivotal paradigm shift in the agricultural landscape, addressing sector challenges and paving the way for a more sustainable, efficient, and resilient future. The IEEE Malaysia Section Humanitarian Activities Committee remains committed to driving positive change through innovative initiatives that bridge technology and sustainability, ultimately contributing to the betterment of communities and fostering a more sustainable world.

(Reported by: Dalila Mat Said & Norhafezaidi Mat Saman)
IEEE Malaysia Section's Humanitarian Activities and Climate Change Committee, in partnership with the Women in Engineering Affinity Group Malaysia, has successfully secured a grant of USD 400 from the R10 WIE Special Support Fund (Climate Change Theme). The grant has been allocated for the implementation of the program titled "Rising to the Challenge: Women Engineers and Climate Change Awareness."

The enlightening program unfolded in a hybrid mode at Universiti Teknologi Malaysia through Webex Cisco on November 23, 2023. The event featured distinguished speakers, Prof. Dr. Sumiani Binti Yusoff and Dr. Nina Diana Binti Nawi, and was conducted in collaboration with the Centre of Electrical Energy Systems at Universiti Teknologi Malaysia and the Centre for Innovation in Medical Engineering at Universiti Malaya.

As the world confronts the impacts of climate change, the unique perspectives and contributions of women in engineering are proving pivotal in shaping innovative solutions. Women engineers are assuming leadership roles in climate-related initiatives, leveraging their skills, expertise, and diverse viewpoints to address environmental challenges.

From spearheading sustainable energy projects to designing climate-resilient infrastructure, women engineers are at the forefront of driving positive change. Women engineers play a crucial role in communicating the urgency of climate action, inspiring individuals and communities to take meaningful steps toward sustainability. Their fresh and inclusive approach to problem-solving contributes to diverse perspectives and innovative thinking, fostering creativity and resilience in the face of environmental challenges.

The collaborative efforts of the IEEE Malaysia Section's Humanitarian Activities and Climate Change Committee, along with the Women in Engineering Affinity Group Malaysia, exemplify the commitment to empowering women engineers in the global fight against climate change.

(Reported by: Dalila Mat Said, Norhafezaidi Mat Saman)
Throughout 2023, IEEE Malaysia Section has organized and been involved in a total of 23 Educational Activities at school, university, district, and national levels, impacted 45307 school pupils, teachers, parents, and others. IEEE Malaysia Section has been appointed as the strategic partner and agency by Ministry of Higher Education Malaysia, Ministry of Education Malaysia, Ministry of Health Malaysia and the Minister of Housing and Local Government Malaysia and Ministry of Science, Technology and Innovation Malaysia for these educational activities.

191 volunteers from Centre of Excellence for Micro System Technology (MiCTEC), Faculty of Electronic Engineering & Technology, Universiti Malaysia Perlis (FKTEN UniMAP), Persatuan Isteri & Kakitangan Wanita UniMAP (PISKANITA), Institute of Nano Electronic Engineering (INEE), UniMAP MySTEM Ambassador Club, IEEE Electron Devices Society Malaysia Chapter, IEEE Sensors & Nanotechnology Joint Councils Chapter, Centre of Excellence for Advanced Computing (AdvComp), Advanced Multidisciplinary MEMS-Based Integrated Electronic NCER Centre of Excellence (AMBIENCE), Institute of Engineering Mathematics (IMK), UniMAP TVET Centre, Faculty of Electrical Engineering & Technology, Universiti Malaysia Perlis (FKTE UniMAP), IEEE Electronics Packaging Society Malaysia Chapter (EPS), IEEE Dielectric and Electrical Insulation Society Malaysia Chapter (DEIS), Faculty of Electronic Engineering & Technology Student Association (PPFKTEN), Intel Kulim 1, Faculty of Mechanical Engineering & Technology, Universiti Malaysia Perlis (FKTM UniMAP) and Faculty of Civil Engineering & Technology, Universiti Malaysia Perlis (FKTA UniMAP).

16 February 2023 – Hari Ko-Kurikulum, Sekolah Kebangsaan Sultan Ahmad Tajuddin.
16 March 2023 – Mini Jelajah Agenda Nasional Malaysia Sihat, Institut Pendidikan Guru Kampus Darulaman.
12 – 13 May 2023 – STEM Showcase, UoW KDU Penang.

9 July 2023 – AI Consortium Launching, Tech Dome Penang.

9 July 2023 – Educational Visit by Sekolah Menengah Kebangsaan Raja Chulan, Faculty of Electronic Engineering and Technology, Universiti Malaysia Perlis.

11 July 2023 – Integrated Design Project Exhibition 2023, Faculty of Electronic Engineering and Technology, Universiti Malaysia Perlis.

26 – 26 August 2023 – STEM Showcase, Han Chiang High School Penang.

10 September 2023 – Wellness Month, Sekolah Menengah Kebangsaan Tanjung Pauh.

10 September 2023 – Reka Bentuk & Teknologi Workshop, Sekolah Kebangsaan Mergong.

23 September 2023 – STEM Showcase and Innovation Challenge, Sekolah Menengah Kebangsaan Dato' Haji Ahmad Said

29 September 2023 – Corporate Social Responsibility, Sekolah Kebangsaan Sena.

2 October 2023 – i-STEM, Sekolah Menengah Kebangsaan Permatang Pasir.

3 November 2023 – Fun with STEM, Maktab Rendah Sains MARA Arau.

16 November 2023 – Karnival GOAL STEM MOSTI, Sekolah Menengah Kebangsaan Gunung Semanggol.

21 November 2023 – STEM with Community, Festival Konvokesyen Universiti Malaysia Perlis.

22 November 2023 – Fun with STEM, Sekolah Kebangsaan Paya Kamunting.

24 November 2023 – Lawatan Penandaarasan Guru Kanan Mata Pelajaran Sains & Matematik PPD Klang, Faculty of Electronic Engineering and Technology, Universiti Malaysia Perlis.

30 November 2023 – SiNDRA Fun & Fund Carnival, Sekolah Kebangsaan Seri Indera.

7 December 2023 – Hari Penjelajahan Robotik dan Inovasi STEM, Sekolah Kebangsaan Felda Chuping.

14 – 15 December 2023 – i-STEM EduAction @ SRIAZ, Sekolah Rendah Islam Al-Azhar.

16 – 18 December 2023 – PSN Xporia Sains 2023, Pusat Sains Negara Cawangan Wilayah Utara

IEEE Malaysia Section Facebook (Photo Album: 2023 Educational Activities)
https://www.facebook.com/share/CWLzqfzEvwF3mQuL/
The annual SYWL Congress, open to all IEEE members, was a prestigious occasion hosted this year at Asia Pacific University, marking a momentous honor for our institution. The event commenced with a seamless registration process, paving the way for Dr. Nordin’s gracious opening remarks, which set an engaging and optimistic tone. Bernard then took the stage to highlight the SYWL activities in Malaysia, showcasing the remarkable achievements and ongoing initiatives. Following by that was Prof Saifur Rahman’s distinguished lecture on IEEE Perspectives related to SYWL, and IEEE Malaysia Section Dinner, providing a convivial atmosphere conducive to networking among the attendees. Subsequently, a captivating Culture Show further enriched the event, celebrating diverse traditions. The networking session continued, fostering connections and idea exchanges until the event concluded at 10:00 PM.
IEEE Students Congress 2023

Date: 5th Nov 2023 (Sunday)

Venue: Dewan Kuliah 2, Bangunan Akademi, Faculty of Engineering & Built Environment, Universiti Kebangsaan Malaysia

The IEEE Students Congress 2023, held successfully on 5th Nov 2023, was a dynamic event attended by 40 students. The event commenced with an inspiring opening speech by Prof. Madya Ir. Dr. Norhana Arsal, the Club Counselor of IEEE UKM SB. The students then delved into the program, which featured a series of enlightening sessions. The program included student congress videos, offering insights into the world of IEEE and its student branches. Two impactful career talks were delivered. "Career Aspirations: Nothing is Impossible!" was presented by Dr. Eu Poh Leng, Senior Director from NXP Semiconductors, and "Navigating Success: Industry Engagement & Insights for Young Professionals" was delivered by Mr. Wong Shaw Fong, Engineering Manager at Intel Corporation. Their talks offered valuable career guidance. In addition, David Chong Teak Wei, Head of AI department at Ever AI Technologies, shared insights in a talk titled "Why Machine Learning?" shedding light on this trending field. The event also featured IEEE Student Branches Networking Videos from IEEE UKM SB, IEEE UM SB, IEEE UiTM SB, and IEEE UNITEN SB. The IEEE Students Congress 2023 concluded with a closing remark by Dr. Nordin Ramli, Chair of IEEE Malaysia Section. It was an engaging and informative event, fostering learning, networking, and career development opportunities for the attending students.
On the 10th of October 2023, IEEE Women in Engineering Malaysia successfully organized the IEEE Malaysia Section Women in Engineering (WIE) Affinity Group Capacity Building, Skills Development and Climate Change Competition, in conjunction with IEEE Day. The event took place in the Cube, Faculty of Engineering, Universiti Malaya. The ceremony was graced with the presence of Celia Shahnaz, WIE Global Chair. The event commenced with a welcome speech from Prof Fatimah Ibrahim, WIE Malaysia Chair. The event was attended by 32 physical participants and 32 virtual attendees. This event is cheered up by Capacity building, Skills Development, and Climate Change quizzes. We congratulate all the winners! The winners are Chen Zhi Han, Aiesya Salabila Mohd Radzuan, and Nur Nida Husna binti Zamani.

The Meet The Leaders Series returns with Series 3. Prof Celia, the WIE Global Chair again was invited to deliver her insights on Capacity Building and Global Funding Opportunities. This talk took place in conjunction with the WAG Capacity Building event. With her expertise and experience, Prof. Celia guided the audience through a journey of capacity building. She delved into the core of personal and professional development, outlining various methods, opportunities, and resources available to the WIE community for enhancing their skills. Her insights were more than just an advice, they were a roadmap to success, and a source of inspiration for those aspiring to reach new heights.

A membership drive was conducted during the WAG Capacity Building, Skills Development, and Climate Change Competition on the 10th of October 2023. The IEEE WIE Student Branch UM has shared the membership perks and benefits of joining both IEEE and WIE in particular. Tokens have been given to those who attended the sharing session. In the end, WIE MY AG hope that the sharing session will attract more members, which could lead to more beneficial activities and moving forward, WIE MY AG will be led by younger generations.
IEEE Day Activities: Science is Fun! With Buku Jalanan Chow Kit

In conjunction with IEEE Day, IEEE Women in Engineering (WIE) Malaysia, supported by EMBS, IEEE-WIE UM Student Branch and Center for Innovation in Medical Engineering, Universiti Malaya, have successfully organized the 'Science is Fun!' activity with Buku Jalanan Chow Kit. The event was held on the 11th of October 2023. The event was led by Prof Ir Ts Datin Dr Wahidah Mansor and assisted by three facilitators from the IEEE WIE UM Student Branch. About 38 students participated in mini-electronics activities. At the end of the event, we delivered a small donation in the form of a bag and a KFC meal to the participants who attended.

IEEE Day Activities: Drone Workshop/Competition

A drone and robotic arm programming workshop has been organized in collaboration with IEEE WIE UM Student Branch on 13 of October 2023. The drone and robotic arm are equipment sponsored under the Erasmus Plus ICT-INOV grant. There were approximately 15 participants in the event. They were also shown how to use the 3D Pen.
On the 27th of October 2023, IEEE Women in Engineering Malaysia successfully organized the Summit on Women in Leadership and Technopreneurship, in conjunction with IEEE Day. The event took place in the Cube, Faculty of Engineering, Universiti Malaya. The summit was flanked by 4 speakers, Assoc Prof Dr Wan Wardatul Amani Wan Salim, Chief Technologist and Founder of nanoSkunkWorkX, Dato’ Frieda Pilus, founder and mentor of Cempaka Group of Schools, Madam Mariatini Othman, Senior Vice President of MTDC and Madam Haslin Ismail, Head of Innovation of Edgenta Mediserve Sdn Bhd. The discussion was moderated by Prof Fatimah Ibrahim, WIE Malaysia Chair. The inspiring talk has been attended by 40 participants from both industries and academia.

IEEE WIE MY AG and IEEE MY Section have joined forces to organize the Meet The Leaders Series 4 cum SYWL (Student, Young Professional, WIE, Life Member) Meet Up with the President, held on 24th October 2023 in Asia Pacific University. The event’s objective was to initiate networking between the IEEE SYWL communities. The IEEE Malaysia community was glad to have the 2023 IEEE President and CEO, Prof Saifur Rahman as the guest of honor. Welcoming remarks were done by Ir Dr. Nordin Ramli, Chair of IEEE MY Section. Ir Dr. Bernard Lim introduced the SYWL activities completed and planned in Malaysia. Prof Saifur then spoke on the directions of SYWL and his passion in leading the IEEE community to greater heights. The event ended with a buffet dinner and a cultural show.
WIE UK & I/ WIE MY Symposium – IEEE Global Communications Conference

Following the collaboration with WIE UK and Eire, WIE MY Affinity Group has organized a WIE Symposium and Workshop, in conjunction with the IEEE Global Communications Conference, which took place in Kuala Lumpur Convention Centre, on 7th of December 2023. Prof Ir Dr Fatimah Ibrahim, Chair of WIE Malaysia, was one of the invited panelists in the IPA 11 session: Accelerating Sustainable Development Goals With IoT Innovation.

Rising To Challenge: Women Engineers and Climate Change Awareness

On 23 November 2023, the IEEE Malaysia Section, Women in Engineering (WIE) and in collaboration with the Centre of Electrical Energy Systems UTM and Center for Innovation in Medical Engineering UM successfully organized a hybrid webinar (face to face & Webex platform) on climate change to explore innovative strategies shaping a greener. More than 30 participants from industries and academia have participated in the events.
IEEE Malaysia Section Young Professionals
IEEE Malaysia Section Life Members Affinity Group

Reported by: Nur Idora Abdul Razak
(Honorary Secretary, nuridora@ieee.org)

IEEE Malaysia Bowling Tournament 2023

The IEEE Bowling Tournament 2023, was held at Wangsa Bowl, Setia City Mall on 3 November 2023. The event was organized by IEEE Malaysia Section and IEEE Malaysia ComSoc/VTS Joint Chapter, funded by IEEE Young Professionals Meet-Up Fund, IEEE Malaysia Section, and IEEE Malaysia ComSoc/VTS Joint Chapter.

It brought together 18 teams with a mix of 72 IEEE members and 28 non-members for a day of friendly competition. UTP Student Branch secured the top spot, followed by Team Rhino and KL Subsection. Individual awards went to Adam Harith Zainal Abidin and Liza Abdul Latiff for Best Male and Female Bowlers, respectively. The tournament's success highlighted the community spirit and camaraderie within the IEEE network. Congratulations to all participants and winners!

Link for photos:
http://tinyurl.com/2023IEEEMYBowl1
http://tinyurl.com/2023IEEEMYBowl2
http://tinyurl.com/2023IEEEMYBowl3

IEEE Malaysia Section Life Members Affinity Group

The Life Members Affinity Group was formed in IEEE Malaysia Section as the fourth Affinity Group on 17th August 2023.
IEEE Kuala Lumpur Subsection
Reported by: Haslina Md Sarkan
(Communications/Publicity/Website Coordinator, haslinams@utm.my)

These invaluable insights were shared in a session which took place at He & She Coffee UTM Kuala Lumpur (UTMKL) Campus, 6th November 2023. Hosted by IEEEMYKL in collaboration with UCSI University’s School of Architecture and Built Environment, this session attracted 27 participants, including IEEE members, students, academics, and industry professionals. The session served as a platform for knowledge exchange and collaborative endeavors, enhancing the global discourse on humanitarian technology.

(Reported by: Khairul Zahreen Mohd Arof)

IEEE DAY & STEM Activities at SK Padang Tembak 2

14th October, 2023 - IEEEEMYKL Subsection collaborated with Jawatankuasa Mahasiswa Kolej Siswa Jaya UTMKL and SK Padang Tembak 2, to organize a Paper Plane Competition, fostering creativity and STEM education awareness among the school children.

The event engaged 5 IEEE members, 1 IEEE student member, 40 primary students, 2 teachers and 20 undergraduates, focusing on aeronautical skills.

A briefing on aviation history preceded a hands-on session, resulting in awards for the longest flights. Top performers received prizes, and the event ended with a celebratory cake cutting in conjunction with IEEE Day.

(Reported by: Khairul Zahreen Mohd Arof)

How Tech Transforms Lives: A Congress Recap And Knowledge Exchange

Rajkot, Gujarat - The IEEE R10 Humanitarian Technology Conference (HTC) 2023, held at Marwadi University from the 16th to the 18th of October, emerged as a successful event, orchestrated by the IEEE Gujarat Section. Representatives IEEEEMYKL, Dr. Khairul Zahreen Mohd Arof and Dr. Mohd Fitri Mohd Yakub, played a prominent role during the conference.

Their active participation was possible thanks to generous sponsorships of transport and accommodations by IEEE R10, Marwadi University, and IEEEEMYKL. These experiences and learnings are expected to play a pivotal role as Kuala Lumpur Subsection gears up to host HTC 2024. The knowledge transfer and collaborative efforts fostered during the event are anticipated to further enhance the impact of the upcoming conference.

(Reported by: Khairul Zahreen Mohd Arof)

Humanitarian And Educational Initiatives – HTC 2023

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(Reported by: Khairul Zahreen Mohd Arof)
Installation EWS System Yan Kedah

28 & 29 October, 2023 - Dr. Fitri and Sharifuddin, both members of IEEE MYKL Subsection, participated in the second phase of a community project aimed at disaster mitigation using cutting-edge technology solutions at Yan Kedah. The two-day event involved the installation of a data-driven emergency warning system (EWS), which sends data to relevant offices in Kuala Lumpur. The technology is expected to have a positive impact on the local community.

(Reported by: Muhamad Sharifuddin bin Abd Rahim)

Pre-u Program: Introduction To Arduino

In collaboration with UTMKL Student Branch, an introductory course on Arduino programming and fundamental electronics was organized for SK Wangsa Maju Zon 10 students. The event, funded by the IEEE Malaysia section and facilitated by 5 members from UTMKL Student Branch and 2 IEEE MYKL Subsection members, aimed to equip the school students with essential skills to ease their transition to secondary school. The program spanned two sessions, conducted on 6th November and 4th December. The students displayed high levels of interaction during the sessions, reflecting a positive impact on their future learning journey.

(Reported by: Muhamad Sharifuddin bin Abd Rahim)
IEEE Malaysia Sarawak Subsection

Reported by: Ong Chin Ann
(Communication and Promotion, ongca@ieee.org)

IEEE Sarawak Q4 Seminar and Workshop Series

IEEE Sarawak Subsection in collaboration with local institutions, student branch, and industry partners have recently co-organized various seminars and workshops series.

These seminars and workshops include the “Industry 4.0 Workshop” which emphasis on Industry-Academia Collaborations and took place on 10 October 2023. While the “IoT4Community 2023” workshop held on the 18 November 2023 followed by the Gamification Seminar and Technical Talk as the year end events for the subsection on the 6 and 7 December respectively.

Do visit https://sarawak.ieeemy.org/ to read more about the activities, seminars, and workshops.

Smart Walker At Trinity Eldercare

Members of the IEEE Sarawak Subsection teamed up with student members from the IEEE Swinburne Sarawak Student Branch for a follow-up visit to the Trinity Eldercare, Kuching, Sarawak to demonstrate the advantages of their Person-Following Ambulatory Assistance Companion Walker and to gather critical feedback for its further development.

This project is part of a larger initiative, Engineering Projects in Community Service (EPICS), designed to foster collaboration between students and seasoned engineering professionals. The project have shown significant potential from assistive technologies, making a tangible impact on users’ lives.

Student Activity on IEEEXtreme 17.0

On October 28, 2023, excitement filled the air at the computer labs of the IEEE Swinburne Sarawak Student Branch as midnight (UTC timezone) marked the start of the IEEEXtreme 17.0 contest.

At the Swinburne Sarawak campus, four teams—Gelato, ProfessionalNoobs, TouchStar, and Book—rose to the challenge, guided by their proctor, IEEE member Isaac Asante.

The IEEE Sarawak Subsection and the IEEE Swinburne Sarawak Student Branch extended their heartfelt congratulations to all the participating students who took part in the flagship event.

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Research Project of Radio Repeater in Royal Belum Rainforest

The Royal Belum State Park in Malaysia is a unique and diverse tropical rainforest. However, some areas faced communication challenges due to a lack of coverage from existing telecommunication towers. With the support of a Sustainable Development Goals (SDG)-themed grant from Universiti Teknologi MARA Malaysia (UiTM), the Antenna Research Centre (ARC), operating under the Deputy Vice Chancellor (Research & Innovation) Office, has launched a project to enhance the communication in Royal Belum. Our project aimed to improve communication in these remote areas by installing a Radio Repeater Station, which acted like a signal booster. We also demonstrated GPS-based tracking using amateur radio. This pilot project aimed to show that our concept could effectively enhance radio communication in the region, benefiting the local community, researchers, and the public. It was particularly crucial for search and rescue efforts in these remote locations. Additionally, the project served as a platform for sharing knowledge between researchers, students, and the community. The initiative combined both research and education components, involving three (3) undergraduate and two (2) postgraduate students, as well as six (6) experienced researchers where four (4) of them are members from IEEE Malaysia Antennas and Propagation/ Microwave Theory and Technology/ Electromagnetic Compatibility Joint Chapter. The project, supported by the Malaysian Amateur Radio Transmitters’ Society (MARTS) and IEEE Malaysia Antennas and Propagation/ Microwave Theory and Technology/ Electromagnetic Compatibility Joint Chapter, addressed communication issues in a practical and community-focused manner.

2024 IEEE Asia-Pacific Conference on Applied Electromagnetics (APACE2024)

The 10th APACE, the 2024 IEEE Asia-Pacific Conference on Applied Electromagnetics (APACE2024) will be held at Langkawi, Malaysia from December 21 to December 23. Fully sponsored by the IEEE AP/MTT/EMC Joint Chapter of Malaysia. Authors are invited to submit contributions for review and possible presentation at the symposium on advancements and innovations in the fields of electromagnetics, antennas, and wave propagation. Paper submission will be managed by EDAS: https://edas.info/N31623. Potential session organizers are welcome to propose specific technical topics, workshops and tutorials. Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore’s scope and quality requirements.
The 2023 IEEE CASS (M) Distinguished Lecturer Programme (DLP), held on October 23rd, 2023 at Thinker Space 2.0, Faculty of Engineering, UPM, was a notable event in the technology sector, attracting attention to the theme of "Intelligent Memory for Efficient Hardware Accelerator." Prof Dr. Baker Mohammad, an IEEE CASS Distinguished Lecturer, delivered an interesting keynote lecture during the event, which took place from 9:00 a.m. to 11:00 a.m. His presentation gave an in-depth examination of intelligent memory systems and their critical role in increasing the efficiency of hardware accelerators, captivating the audience with his knowledge and engaging delivery.

The audience consisted of 41 people, comprising 26 students, 10 academics, and 5 industry professionals. This combination highlighted the younger generation's interest in technical breakthroughs, the academic community's commitment to staying current with cutting-edge research, and the subject's relevance in the industrial realm. The event was held at Thinker Space 2.0, a new location that provided a great environment for learning and engagement, significantly improving the attendees' experience.

The event was originally scheduled to take place in person, but due to the ongoing conflict in the Middle East, it is instead taking place online. Overall, 2023 IEEE CASS (M) DLP was a huge success, signifying a crucial step forward in academia and industry collaboration in the sphere of technology and innovation. It not only provided vital insights into intelligent memory systems, but it also promoted a sense of community and collaboration among students, academics, and industry experts, highlighting IEEE CASS's critical role in bridging knowledge gaps and accelerating future technological developments. Three new CAS members were registered as a result of the event.
The 2023 IEEE CASS (M) under IEEE CAS Distinguished Lecturer Programme (DLP) successfully hosted an informative talk titled "Bringing Cores Closer Together: The Wireless Revolution In On-Chip Communication" on December 4, 2023. The event, which was held online through Google Meet, featured a crucial discussion by Prof. Dr. Partha Pratim Pande, a respected figure in computer engineering from Washington State University. The event drew a broad audience of 30 people, including 12 students, 12 academics, and 6 industry workers, reflecting a mix of new and seasoned brains in the subject.

Prof. Dr. Pande’s lecture focused on emerging developments in on-chip communication, with a special emphasis on the role of wireless technologies in improving chip performance and efficiency. His insights into how wireless solutions might transform chip design were especially illuminating, providing a new viewpoint on overcoming the limitations of standard wired communication techniques. Attendees engaged in meaningful conversations and sought Prof. Pande’s advice on many areas of wireless on-chip communication during the interactive Q&A phase, which further enriched the programme.

The event was a big step forward in the exchange of knowledge and the promotion of discourse among students, academics, and industry professionals. The contributions of Prof. Dr. Pande are likely to encourage future research and breakthroughs in on-chip communication technology. Overall, the 2023 IEEE CASS (M) DLP session served as a catalyst for future partnerships and breakthroughs in the field of circuit and system for computer engineering.

Prepared by Asral Bahari
The IEEE Circuits and Systems 2023 Seasonal School on Devices and Wearables was held from 12th - 15th December 2023 at the UPM-NI Embedded Systems Engineering Laboratory in the Faculty of Engineering, Universiti Putra Malaysia. This event was sponsored by IEEE Circuits and Systems and supported by the Faculty of Engineering, Universiti Putra Malaysia.

The seasonal school introduced participants on the latest devices and wearables using shape memory alloy, a type of smart material with huge potential to replace conventional actuator. The speakers included academicians and industry expert from Universiti Putra Malaysia, Prince Songkla University, Thailand and VISI Academy. The seasonal school was attended by undergraduate students, postgraduate students as well as academicians from various universities in Malaysia as well as Thailand.

The focus of the seasonal school was on the fundamental theory of shape memory alloy material, design of the shape memory alloy actuator for different applications. Highlights on current devices and wearables using shape memory alloy and other potential applications were also presented. This seasonal school consists of lectures, demonstrations, hands-on sessions and a case study where the participants designed a prototype of device or wearable using shape memory alloy.

This seasonal school achieved its objective in providing new knowledge on cutting edge technology for devices and wearables, and at the same time promoting the IEEE Circuit and Systems Society among the participants. The participation of members from Thailand achieved regional impact and wider dissemination of knowledge. The networking opportunity fostered future collaboration among participants as they embark in research related to topics presented in the seasonal school.

Reported by Ermira Junita Abdullah
The IEEE Circuits and Systems Society (CASS) Malaysia Chapter has successfully organized the IEEE CAS Seasonal School on AI Integrated Circuits and Systems for Medical and Surgery Technologies. The first series of this seasonal school was co-organised in conjunction with the Summer Course on Computer Science event in Institut Pertanian Bogor, Indonesia on the 12th October 2023. The second series (main event) of the seasonal school was conducted on the 15th and 16th November 2023 in Universiti Putra Malaysia. These programs have directly impacted 97 registered participants who already physically join the program and expect to impact more online participation, societies and publics once the virtual recorded video is shared online.

The seasonal school aims to offer the students, researchers, practitioners, and experts to share about the state-of-the-art in applying artificial intelligence and machine learning to modern AI integrated chip design and design of automation systems. The program was delivered by the invited distinguished speakers from both academia and industries for professional and technical talks. Besides that, a hands-on workshop on deep learning for liver segmentation was organized under this program. This seasonal school highlighted the three pillars which are (1) OpenCV for Image processing, (2) Pattern recognition using Deep Learning, and (3) Integrated Artificial Intelligence Analog Circuits Design. These topics were the main focus and highlight during the seasonal school. Experts, researchers, practitioners and students were gathered and connected to exchange their knowledge in the highlighted topics. This seasonal school was a joint program and co-partnered with industry and academic institutions. Thank you to IEEE CAS for financing these events through the seasonal school funds initiative.
The 2023 15th International Conference on Software, Knowledge, Information Management and Applications (SKIMA 2023) traces its roots to a collaborative effort that began in 2006, uniting research professionals from Western and Asian countries. The 2023 edition of SKIMA took place at the Corus Hotel, Kuala Lumpur, from 8 to 9 December 2023, with IEEE ComSoc/VTS as the technical co-sponsor. This year’s SKIMA was well-attended and supported by around 80 experts and researchers from all over the world such as Malaysia, France, Portugal, United Kingdom, Thailand, Indonesia, Bhutan, Nepal, Maldives, Bangladesh, and Kazakhstan. The technical program of this conference is divided into different track fields, consisting of 6 regular sessions, 1 hybrid session and 2 virtual sessions. There was also a Workshop-Cum-Training session on the Safety and Assurance of Artificial Intelligence Systems. This year, SKIMA is honoured to have 2 keynote speakers from different countries, Prof. Ir. Dr. Mohammad Faizal Ahmad Fauzi from Multimedia University, Malaysia and Prof. Khondaker A. Mamun from United International University, Bangladesh. The highlight of the conference was the grand dinner where international participants enjoyed beautiful Malay dance performances from the Cultural Club, Sekolah Menengah Kebangsaan Aminuddin Baki, Kuala Lumpur.

Belajar Sains dan Teknologi (Be.S.T) is an annual education initiative organized by the IEEE Malaysia ComSoc/VTS Joint Chapter. This program serves as a platform to introduce students, particularly those in primary and secondary schools, to the latest advancements in communication technology. The primary objective of this program is to provide exposure to students and educators, fostering interest and curiosity in the dynamic field of communication engineering. IEEE Malaysia ComSoc/VTS Joint Chapter collaborated with the PPD Bera to extend the reach of this program and offer more opportunities for students and teachers to participate. This program was held online via the YouTube platform every Saturday throughout the month of October 2023, drawing a substantial audience of 1214 participants from across Malaysia. The program featured four knowledge-sharing sessions covering topics such as antennas, drone technology, V2X, and satellites. Following each sharing session, a pop-quiz was conducted at the conclusion of the program to evaluate participants’ comprehension of the presented topics. These quiz sessions utilized the Quizizz application, with 5 winners chosen for each session.

(Reported by: Nor Aishah Muhammad)
IEEE ComSoc/VTS Malaysia orchestrated a successful industry visit to the Mranti 5G lab on October 25, 2023. The delegation comprised esteemed academicians and industry members from various regions across Malaysia. The team received a warm welcome from En. Najib Zulkifli, Head of Emerging Tech and Innovation, who provided a comprehensive briefing on the advancements at Mranti 5G lab.

During the briefing, En. Najib shared exciting news about MRANTI PARK’s upcoming 5G enterprise facility. He emphasized that the MRANTI 5G Experience Centre would soon offer a purpose-built environment for enterprises. En. Najib stated, "The MRANTI 5G Experience Centre unlocks the potential for a wide variety of use cases, aiding corporations in meeting sustainability goals and improving supply chain management – both critical agendas for investors and the public alike."

The Centre is poised to feature a prototyping, test, demo, and lab area with speeds reaching up to 1GBps, showcasing industry applications and use cases across various vertical sectors. The event featured impressive showcases by industry leaders, including Redtone on Smart Farming, Xts on Smart Manufacturing, BNetworks on HealthTech Solutions, CelcomDigi on Security Surveillance, and Universiti Teknologi Malaysia on Flood Drone Monitoring. MRANTI encourages infrastructure service providers, telcos, and enterprises interested in partnerships, 5G Proof-of-Concept testing, exploring 5G solutions, or gaining insights into applied 5G to connect with them. MRANTI Park promises innovators the ability to leverage ultra-fast 5G data networks, enhancing communication efficiency with higher data rates, lower latency, increased connection density for reliability and coverage, and improved position accuracy to support higher user mobility. Besides 5G lab, the team also got a chance to explore the MAKER lab which is offer the prototyping services. MRANTI MakersLab offers quick, affordable access to tools, equipment or inspiration for future innovators and thinkers. As the country’s one-stop powerhouse, their aim is to serve the community by providing a space to collaborate, learn, and materialise solutions using MakersLab facilities.
IEEE Global Communications Conference (Globecom) 2023, Kuala Lumpur

IEEE Global Communications Conference (Globecom) is one of the IEEE Communications Society’s two flagship conferences dedicated to driving innovation in nearly every aspect of communications. Each year, more than 3000 scientific researchers and their management submit proposals for program sessions to be held at the annual conference.

For 2023, the warm and wonderful city of Kuala Lumpur, Malaysia had been selected to host IEEE GLOBECOM from 4 to 8 December 2023. Themed “Intelligent Communications for Shared Prosperity” this flagship conference of the IEEE Communications Society featured a comprehensive high-quality technical program including 13 symposia and a variety of tutorials and workshops. IEEE GLOBECOM 2023 also included an attractive Industry program, with keynotes and panels from prominent research, industry and government leaders, business and industry panels, and vendor exhibits.

This year’s Globecom has received the second highest number of paper submissions in the history of any ComSoc conferences. Out of those about 1500 papers were accepted for presentation and nearly 2400 people registered as attendees.
The IEEE Malaysia Comsoc/ VTS joint chapter had successfully organised the 16th Malaysia International Conference on Communications (MICC 2023) at Kuala Lumpur, Malaysia from 10th to 12th December 2023. MICC 2023 is a biennial conference technical sponsored by the IEEE Malaysia Comsoc/ VTS joint chapter with 30 years of track record. This year, the conference theme of "Smart Digital Communication for Humanity" promoting responsible use of intelligent and innovative next-generation technologies for good.

A total of 75 attendees from 7 countries including UK, Canada, China, India, South Korea, Japan, UAE and Malaysia attended the physical conference this year.

The programme of MICC 2023 began at the Universiti Teknologi Malaysia Kuala Lumpur Campus with three Tutorials on the topics of 6G, Machine Learning, Fluid Antenna Systems and V2X, presented by speakers from Malaysia and UK.

The second day programme at the Concorde Hotel Kuala Lumpur started with two opening keynotes on the emerging topics of Fluid Antennas Multiple Access and Ultra Reliable and Low Latency Communication, delivered by eminent keynote speakers Prof Kai-Kit Wong from UCL UK and Prof Yonghui Li from University of Sydney, Australia, respectively. The programme then continued with the industry forum by invited industry panels from telecom industry.

A total of 29 accepted papers which stood out among the 51 submitted papers were presented through the 6 technical sessions. Best presenters were awarded for outstanding presentation in each of the technical sessions.

The conference programme drew the curtain on 12th December with positive and satisfied feedback from attendees. The next MICC conference is expected to take place in 2025.
On 31st October 2023, Prof. Yejun He from Shenzhen University, China & National University of Singapore has given a technical talk on "Research of 5G mmWave Base Station Antenna" at Faculty of Engineering, Multimedia University. He also spent some of his time to visit the labs at MMU as well as having a discussion with faculty members on possible future collaboration.

Prof. Dr. Shui Yu from the University of Technology Sydney, Australia provided two talks on 8th December 2023. The first talk was on “Digital Privacy: Status, Challenges, and Directions” at Asia Pacific University of Technology & Innovation (APU) while the second talk was on “High Quality Paper Writing - Persuasive Writing with Evidence” at Universiti Tunku Abdul Rahman (UTAR) Sungai Long Campus and co-organized with the IEEE Council on RFID Malaysia Chapter.
On 7th December 2023, the 6G Seminar Series on Next Generation Multiple Access were delivered by two distinguished IEEE Fellows: Prof Kai-Kit Wong and Prof Zhiguo Ding. This program was jointly organised by the Wireless Communication Centre, Universiti Teknologi Malaysia and the IEEE Malaysia Communication Society and Vehicular Technology Society Joint Chapter. The first talk was on “Opportunistic fluid antenna multiple access using team-theoretic deep reinforcement learning” by Prof Dr Kai-Kit Wong, an IEEE Fellow from the University College London while the second talk was on “NOMA Assisted Far-Field and Near-Field Communications” by Prof Dr Zhiguo Ding, an IEEE Fellow from the University of Manchester.

The IEEE Malaysia Communications Society & Vehicular Technology Society (ComSoc/VTS) joint Chapter together with the Wireless Communication Centre, Universiti Teknologi Malaysia (UTM) had organized the “6G Seminar Series: Reconfigurable Intelligent Surfaces and Photonics” on 26th December 2023 at the Innovation Centre for 5G, UTM KL. There were two talks delivered by distinguished speakers from the University of Surrey. The first talk was on “Reconfigurable Intelligent Surfaces for 5G/6G Coverage Enhancement” by Dr. Mohsen Khalily while the second talk was on “Navigating the Future of Photonics: Exploring Line-Wave Interactions in Photonic Topological Insulators and Devices” by Dr. Maryam Khodadadi.
On 12th December 2023, the Wireless Communication Centre, Universiti Teknologi Malaysia (UTM) and the IEEE Malaysia Communication Society and Vehicular Technology Society Joint Chapter organized the “V2X Seminar Series: Next Generation Vehicular Communications” at UTM KL. Two distinguished speakers have delivered the talk during this event. The first talk on “Starting from V2X towards a World of Opportunities for Cooperation” was delivered by Prof. Periklis Chatzimisios from International Hellenic University and the second talk on “Multi-agent Context Learning (MACOL) for Interference-Aware Beam Allocation in mmWave Vehicular Communications” by Assoc. Prof. Dr. Chuan Heng Foh from the University of Surrey.

On 11th December 2023, the IEEE Malaysia Communications Society & Vehicular Technology Society (ComSoc/VTS) joint Chapter together with the IEEE Universiti Malaya Student Branch (IEEE UMSB) had organized a technical talk by Prof. Yonghui Li from the University of Sydney, Australia on the topic "Beyond 5G towards a Super-connected World".
Technical Talk on "Data-driven and Light-weight ML Aided Smart IoT" by Prof. Dr. Swades De on 5th December 2023 at UTM KL

Student Development Program Through Innovative Robotics for Science, Technology and Innovation (STI ROBOTIK) 2023 on 30th November 2023

Technical Talk on "Data-driven and Light-weight ML Aided Smart IoT" by Prof. Dr. Swades De, Indian Institute of Technology Delhi, New Delhi, India co-organized by the IEEE Malaysia Communications Society & Vehicular Technology Society (ComSoc/VTS) joint Chapter together with the Ubiquitous Broadband Access Network (U-BAN) Research Group, Universiti Teknologi Malaysia (UTM) Kuala Lumpur Campus and IEEE KL Subsection on 5th December 2023 (Tuesday) 10:00am - 12:00 pm (GMT+8) at the Seminar Room 3, BATC, Universiti Teknologi Malaysia (UTM) Kuala Lumpur Campus.

Student Development Program Through Innovative Robotics for Science, Technology and Innovation (STI ROBOTIK) 2023, organized by the Parents and Teachers Association (PIBG) of Kampong Raja National School, Ministry of Science, Technology and Innovation (MOSTI), Informatics and Mathematical Sciences Graduate Association (PRISMA), Universiti Malaysia Terengganu (UMT) and IEEE Malaysia Communications & Vehicular Technology Joint Chapter. The event took place at Sekolah Kebangsaan Kampong Raja, Besut, Terengganu on 30th November 2023.
The Internship Poster Exhibition Week was held from 6 Nov to 10 Nov 2023 at the School of Electrical and Electronic Engineering, Universiti Sains Malaysia, Engineering Campus, Pulau Pinang. 203 students who have completed their internship in 2023 participated in this event. During the event, students need to showcase their posters and give presentation, which evaluated by the lecturers. The best six internship posters were selected by the panels and the prizes awarded was supported by the IEEE Control System Society Malaysia Chapter.

Jointly-co-organized activity between IEEE Control Systems Society Malaysia Chapter and IMechE HWUM Student Chapter for a 3-session Hardware Programming Workshop series to 30-35 engineering students that took place in Heriot-Watt University Malaysia.

The 2023 IEEE 13th International Conference on System Engineering and Technology (ICSET 2023) provides an excellent platform for knowledge exchange between postgraduates & researchers working in many areas. In addition, the conference provides an opportunity for participants from Malaysia and overseas to share research findings and establish network and collaborations.

The IEEE Malaysia Section Control Systems Chapter is proud to organize The 2023 11th IEEE Conference on Systems, Process & Control (ICSPC 2023) organized by The IEEE Malaysia Section Control Systems Chapter. ICSPC 2023 was held in Malacca, Malaysia on the 16th of December 2023 focusing on control, robotics and automation, etc.
Briefing of IEEE and DEIS by DEIS MY Chair

As the DEIS Malaysia Chair, Associate Professor Ir. Dr. Hazlee Azil Illias are invited to present this presentation providing an overview of the activities, initiatives & the role of the DEIS within the broader scope of IEEE at Universiti Tun Hussein Onn Malaysia (UTHM). It was attended by a total number of 30 UTHM students and 20 IEEE members.

Hi Tea for DEIS Members

A Hi-Tea took place on 6 November at Kanzu Academy, UTHM. The Hi-Tea for DEIS members was a resounding success, offering a platform for members to engage, network, and share their expertise and experiences within the realm of dielectrics and electrical insulation. The relaxed setting facilitated meaningful interactions and laid the groundwork for potential collaborations among members.

Technical Talk: Introduction to MOBILISE system

Assoc. Assoc. Prof. Sr. Dr. Noralfishah Sulaiman (Head of Focus Group, Resilient Built Environment, UTHM) was invited to present this presentation providing an overview of the activities, initiatives, and the role of the Kanze academy and disaster mitigation method.

Visit to TNB PMU 500/275kV Yong Peng East

The facility, located at PMU 500/275kV Yong Peng East (YGPE), 85400 Yong Peng, Johor, Malaysia served as an excellent learning ground for understanding the practical application of electrical insulation in high voltage power systems. The primary objective of the visit was to provide DEIS members with a practical, real-world understanding of high voltage power management, electrical insulation, and the application of dielectric materials in the power transmission and distribution sector.
The Distinguished Lecturer Series 2023, organized by IEEE EDS Malaysia Chapter, featured an engaging presentation titled "Multifunctional Materials for Emerging Technologies" by Prof. Dr. Federico Rosei from the Centre for Energy, Materials and Telecommunications at Institut National de la Recherche Scientifique in Varennes, Canada. The event took place on October 4th, 2023, from 10:00 am to 12:00 pm (MYT) at the Thinker Space 2.0, located within the Faculty of Engineering at University Putra Malaysia (UPM). The event drew an audience of approximately 25 participants, comprising lecturers, postgraduate, and undergraduate students from the Faculty of Engineering at UPM. Notably, the event was conducted both physically and through an online platform, facilitating broader participation. The lecture captivated the audience, receiving positive feedback as attendees found the content to be both interesting and informative. The event proved to be a successful and enriching event. The combination of a distinguished speaker, engaging content, and active participation from the audience contributed to its overall success. (Reported by: Haslina Jaafar)
IEEE Electron Devices Society

Reported by: Nurul Ezaila Alias (Honorary Secretary, ezaila@fke.utm.my)

On October 25th, 2023, the STEM4FUN: STEM FOR ALL program in conjunction with Kuala Lumpur State Education Department STEM Convention was executed in collaboration with Universiti Teknologi MARA (UiTM) final-year students pursuing a Bachelor's Degree in Electronic Engineering with Honors. Led by Assoc. Prof Ir. Dr. Ahmad Sabirin Zoolfakar and Ir. Dr. Maizatul Zolkapli, the program sought to spark interest in STEM subjects among mainstream and Special Integrated Education Program (PPKI) students from 32 schools in Kuala Lumpur. Running from 8:00 am to 1:00 pm, the program engaged a total of 102 students organized into 40 groups, each receiving guidance from UiTM students. This collaborative effort aimed to provide hands-on STEM experiences and explore fundamental concepts, fostering interaction between mainstream and PPKI students. The program’s effectiveness in imparting knowledge, enhancing critical thinking, and honing practical skills is evident. (Reported by: Maizatul Zolkapli, Ahmad Sabirin Zoolfakar, Rozina Abdul Rani and Azrif Manut)

IEEE EDS Design your own PCB circuit with Eagle

A hands-on workshop for school community in Sabak Bernam was successfully conducted on 15 and 16 November 2023. The involvement of 6 secondary schools (30 students and 6 teachers) and 5 primary schools (30 students and 5 teachers) during the two days’ workshop has opened a new path of learning materials for the teacher and student in designing their own Printed Circuit Board (PCB) circuit and experienced soldering the designed PCB board. The participants were exposed to the EAGLE software for the schematic circuit drawing and the PCB design. The teaching begins with the basics of drawing schematic diagrams by selecting appropriate components, adding components to the EAGLE library, and connecting the circuit correctly. Participants are required to design the PCB by arranging components on the PCB board.

Once the PCB design is completed, participants have the opportunity to place components on the finished PCB board. Participants were very excited when their circuit successfully activated the blinking LEDs. The PCB board was then turned into a keychain. The program was funded by IEEE Pre-U STEM program. (Reported by: Zurita Zulkifli and Sukreen Hana Herman)

STEM4FUN: STEM FOR ALL Program Leaves A Good Impression on Mainstream and Special Integrated Education Program (PPKI) Students From 32 Schools in Kuala Lumpur

On October 25th, 2023, the STEM4FUN: STEM FOR ALL program in conjunction with Kuala Lumpur State Education Department STEM Convention was executed in collaboration with Universiti Teknologi MARA (UiTM) final-year students pursuing a Bachelor’s Degree in Electronic Engineering with Honors. Led by Assoc. Prof Ir. Dr. Ahmad Sabirin Zoolfakar and Ir. Dr. Maizatul Zolkapli, the program sought to spark interest in STEM subjects among mainstream and Special Integrated Education Program (PPKI) students from 32 schools in Kuala Lumpur. Running from 8:00 am to 1:00 pm, the program engaged a total of 102 students organized into 40 groups, each receiving guidance from UiTM students. This collaborative effort aimed to provide hands-on STEM experiences and explore fundamental concepts, fostering interaction between mainstream and PPKI students. The program’s effectiveness in imparting knowledge, enhancing critical thinking, and honing practical skills is evident. (Reported by: Maizatul Zolkapli, Ahmad Sabirin Zoolfakar, Rozina Abdul Rani and Azrif Manut)

By actively involving and inspiring students in STEM subjects from a young age, they are better prepared for future academic pursuits and potential STEM careers. Ultimately, this contributes to an increase in students pursuing STEM-based occupations, significantly advancing the country’s progress and development by building a skilled workforce in these domains.
In conjunction with IEEE Day, IEEE-EMBS Malaysia Chapter Page and IEEE Women in Engineering (WIE) Malaysia, supported by IEEE-WIE UM Student Branch and Center for Innovation in Medical Engineering, Universiti Malaya, had successfully organized the 'Science is Fun!' activity with Buku Jalanan Chow Kit. The event was held on 11 October 2023.

The event was led by Prof Ir Datin Dr Wahidah Mansor and assisted by three facilitators. The event was fruitful with 38 students participated in mini-electronics activities. At the end of the event, we delivered a small donation in the form of a bag and a KFC meal to the participants who attended.

(Reported by: Nurul Fauzani Jamaluddin)

The IEEE EMBS Malaysia Chapter announced the 2023 Research Excellence Awards and received numerous applications. The awards was organized to recognize excellent research work conducted in the biomedical engineering field. The award ceremony was held on 1st November 2023, in conjunction with the First MyEMBS Summit at Universiti Putra Malaysia. Congratulations to all award recipients!

a. Best Paper Award (Student) : Ahmad Bukhari – UTP
b. Best Paper Award (Junior Researcher) : Nor Salwa Damanhuri – UiTM
c. Best Paper Award (Senior Researcher) : Ibrahim Faye – UTP
d. Publication Excellence Award (Junior Researcher) : Chee Pei Song – UTAR
e. Publication Excellence Award (Senior Researcher) : Tang Tong Boon – UTP

MyEMBS would like to thank all who have submitted their applications. We wish everyone the best in your ongoing research endeavors.
IEEE EPS Visit to Industry at Central Malaysia – NXP Petaling Jaya

As part of IEEE Malaysia and EPS Malaysia effort to visit industry at Central Malaysia, the committee has organized a visit to NXP Petaling Jaya on the 10th of Oct 2023 from 10am to 1.30pm. It was a meaningful event where IEEE EPS Malaysia committee and members had the opportunity to tour NXP factory to understand the history and achievements of the company, and its contribution to the world through a wide range of semiconductor products for Automotive, Industrial IOT, Mobile and Communication Infrastructure to make the connected world better, safer and more secure.

Dr Eu Poh Leng who is the Senior Director of Package Innovation in NXP and the Chairlady of IEEE EPS Malaysia 2023 has hosted the visit together with NXP HR department. Mr Norazham Mohd Sukemi who is NXP’s Principal Staff Engineer and IEEE EPS Malaysia Technical Talk Committee was the MC of the event. After about 1hr tour, the team gathered in the main auditorium at 11am where Dr Eu presented an introduction to NXP Semiconductors. The highlight of the event is a great sharing by Dr YY Tan on Market Trend in Advanced Packaging. Dr YY Tan is from Yole Intelligence and the Past Chair of IEEE EPS Malaysia. About 80 NXP engineers attended the technical sharing in NXP auditorium. After the technical talk, IEEE EPS Malaysia presented a token of appreciation to NXP. NXP HR department also presented a token of appreciation to every visitor. After the technical talk, all visitors adjourned to NXP Cafeteria for lunch, also as a token of appreciation from NXP.

This visit is part of IEEE Malaysia and EPS Malaysia’s 2023 effort to foster stronger relationship with the industry and provide exposure to IEEE EPS members. Indeed, it was a successful event, and the objective has been well achieved. Thx to the GM and HR department of NXP Malaysia for the great support.

(Reported by: Dr Eu Poh Leng)
IEEE EPS Malaysia has successfully organized a full-day Advanced Packaging Workshop at South (Bangi Resort Hotel, Selangor) and North (Eastin Hotel, Penang) regions on Oct 17th and Oct 19th respectively. The event was well received with overwhelming participation from industry located around the region.

The program started with presentation by Dr. Tanja Braun who is Group Manager Fraunhofer IZM Berlin, Germany. She delivered an exciting topic which very relevant to current trend in industry which is “Material and Process Trends in Fan-out WLP and PLP”. The presentation discussed recent technical developments on FOWLP and advantages and challenges in moving to large panel level manufacturing.

To facilitate inspiration, engagement, and advancement of women in technical disciplines, IEEE EPS Malaysia is taking the opportunity to have a short panel discussion with the speakers as well as invited panelists from industry and academic to share their journey and career experience as women in engineering. The two panelists invited in the panel discussion for South region includes Ms. Olivia Ng, Operation Director of Panel Level Packaging from STMicroelectronics and Dr Hafisoh Ahmad, a Senior Lecturer in Electrical & Electronic Engineering Programme at Taylor's University. Panelists for North region are Ms. Rozalia Beica, CSO and VP Strategic Marketing & Business Development at AT&S and Ir. Dr. Banu Poobalan, a Senior Lecturer in Faculty of Electronic Engineering & Technology at Universiti Malaysia Perlis. Dr. Eu Poh Leng wo is the current IEEE EPS Malaysia Chairlady was a moderator of the session at both regions. The panel discussion is in line with global effort in promoting diversity, equity, and inclusion towards increasing female engineers’ talent pool as diverse talents to innovate for the benefit of humanity.
The workshop continues with second renown speaker E. Jan Vardaman, who is President and Founder of TechSearch International, Inc. USA. Two topics were presented, “Exploring Chiplets and the New Era of Advanced Packaging” and “Automotive Packaging Trends”. Her presentation includes chiplets definition and provides examples of the applications and packages types in use today and what is expected for future. Packaging challenges were highlighted and areas that require future work were also documented. She ended her presentation with highlighting drivers and packaging trend for automotive application including infrastructure and material challenges that the industry face.

All in all, the event was well organized and the choice of venue for both events were adequate to accommodate participants majority from industry players around the selected regions. The topics discussed were well received and relevant to the audiences. This could be observed through active participation during Q&A sessions.
UK-Malaysia Semiconductor Roundtable

The UK-Malaysia Semiconductor Roundtable Discussion, held on 31st Oct 2023, at E&O Hotel, Penang, Malaysia provided a platform for stakeholders from both countries to engage in a constructive dialogue about the semiconductor industry. The meeting was moderated by Bok Eng, Shaw Fong and Benard who represented MINDS and IEEE Malaysia Section, which all the focus was aimed to foster collaboration, knowledge exchange, and explore opportunities for growth in this critical sector.

Some key highlights included: Industry Policy Overview sharing by both the UK and Malaysia government officials on the strategic importance of the semiconductor industry in global technology development. The participants subsequently shared insights into the recent trends and technological advancements within the semiconductor sector. The identified collaboration opportunities covering the talent development and supply chain management on advanced packaging, compound semiconductor and design innovations. Representatives from the UK and Malaysia discussed the regulatory challenges, such as export controls and intellectual property protection, were addressed. The need for a conducive regulatory environment to facilitate collaboration and innovation was highlighted.

As the next steps, the roundtable participants agreed to form working groups to further explore the identified collaboration areas, develop action plans, and monitor progress. Future meetings and exchanges were proposed to maintain the momentum and deepen the partnership between the UK and Malaysia in the semiconductor industry.

This UK-Malaysia Semiconductor Roundtable Discussion was a constructive and forward-looking dialogue that identified numerous opportunities for collaboration and growth within the semiconductor industry. Participants highlighted the importance of strengthening supply chains, investing in research and innovation, and addressing regulatory challenges. The commitment to forming working groups and continuing the conversation demonstrates a dedication to realizing the full potential of this partnership and advancing the semiconductor industry in both nations. The event was concluded with a special networking session which was jointed attended by the Chief Minister of Penang, Chow Kuan Yew to also officiated the launching of “UK Semiconductor Handbook”.

(Reported by: Bernard Lim and Dr Wong Shaw Fong)
IEEE EPS Nottingham University Student Chapter & Taylor's University Visit to NXP PJ

IEEE EPS Malaysia has successfully partnered with Nottingham University Malaysia to form IEEE EPS Student Chapter in Oct 2023. The very first activity organized by the student chapter is an industry visit to NXP Petaling Jaya. At the same time, IEEE EPS Malaysia is also in the midst of forming a student chapter with Taylor’s University Malaysia. This visit to NXP Petaling Jaya was organized by IEEE EPS Malaysia and NXP Petaling Jaya, together with both universities to provide exposure about semiconductor packaging and career aspiration to engineering students.

Together with NXP HR department, Dr Eu Poh Leng who is the Senior Director of Package Innovation in NXP and the Chairlady of IEEE EPS Malaysia 2023 has hosted the visit of Nottingham University on Nov 14th, while Mr Norazham Mohd Sukemi who is NXP Principal Staff Engineer and IEEE EPS Malaysia Technical Talk Committee has hosted the visit of Taylor’s University on Nov 21st. Total 20 students from each university and several lecturers joined the visit. Both universities presented a token of appreciation to NXP. NXP HR department also presented a token of appreciation to every visitor. After the technical talk, all visitors adjourned to NXP Cafeteria for lunch, also as a token of appreciation from NXP.

Both events were successful, and the objective has been well achieved. Thx to the GM and HR department of NXP Malaysia for the great support.

(Reported by: Dr Eu Poh Leng)
An international technical symposium with the theme "Emerging Trends in Semiconductor Technology" was held on 29th of November, 2023. This event was organized by the Centre of Excellence in Microsystem Technology (MiCTEC), Universiti Malaysia Perlis. Co-organizers comprised the IEEE Electronics Packaging Society (EPS) Malaysia, Malaysia Board of Technology (MBOT), IEEE Nano Sensors Council, Faculty of Electronic Engineering & Technology (FTKEN), and Institute of Nano Electronic Engineering. The technical symposium covered the following scopes: System design, MEMs, digital circuit design, materials and devices, optoelectronic, analogue, RF IC design, fabrication, characterization, packaging, and testing of electronic devices. The speakers of this event includes individuals with diverse industrial and academic backgrounds. Each participant received an e-certificate from MBOT awarding them five hours of Continuing Professional Development (CPD).

Professor Dr. Azrul Azlan Hamzah, representing Institut Kejuruteraan Mikro dan Nanoelektronik (IMEN), Universiti Kebangsaan Malaysia, delivered the inaugural keynote address. His subject matter was “Extreme Mechanical Properties of MEMS Microphones and Micropumps For Special Applications.” A subsequent presentation entitled “Introduction to More than Moore (Co-design with System)” by Associate Professor Arjuna Marzuki of the School of Technology and Engineering Science, Wawasan Open University.

Mr. Ahmad Shauqi Abdul Halim, Product Development from OSRAM Opto Semiconductors (Malaysia) Sdn. Bhd, discussed on “Exploring LEDs: Trends and Technology.” On the other hand, Dr. Lalin L. Laudis of Mar Ephraem College of Engineering and Technology discussed about "Nature-inspired Computing for VLSI Design." Prof. Ir. Dr. Harikrishnan Ramiah from the Faculty of Engineering, University of Malaya, presented on “Harvesting Power from the Ambient: Multiband RF Energy Harvesting with Distinguished Matching and Rectification." This is followed by Dr. Eu Poh Leng, representing Package Innovation at NXP Semiconductors, then delivered a presentation titled “Advanced Semiconductor Packaging for a Smarter World." Assoc. Prof. Ts. Dr. Rohana binti Sapawi from the Faculty of Engineering at Universiti Malaysia Sarawak (UNIMAS) presented a topic on “Design of a 3.1–10.6 GHz UWB CMOS Power Amplifier Using Cascade Topology." In the concluding segment, Ts. Dr. Mohd Rofei Mat Hussin from Technology Development at the MIMOS Semiconductor Technology Centre (STC) delivered a presentation titled “Recent Progress of Wide-Bandgap Semiconductor Research for Power Electronic Applications” in Malaysia.

This event was well organized and received much attention from industry, academicians, and international participants. In conclusion, the quality and quantity of late-breaking developments in emerging trends in semiconductor technologies truly inspired all attendees of this technical symposium. Congratulations to Universiti Malaysia Perlis (UniMAP) for the continued commitment and support of this inspiring event, joining hands with the EPS Malaysia Section.

(Reported by: Dr Banu)
IEEE EPS Malaysia took an initiative to provide exposure about IC packaging to engineering students from IMechE (Institute of Mechanical Engineering) University Malaya Student Chapter. A one-day short course was designed to suit third and final year students (80% of the participants) to meet the objective. Majority (88%) are Mechanical Engineering students while remaining majoring in Electrical Engineering. The course focusing on flip chip packages which is one of the advanced package family in semiconductor packaging which relevant to current needs. It covers the history, main processes, critical attributes, and common defects of flip chip packages.

Total of 53 students including IMechE committee enroll to the short course. Besides the topic, students were also been introduced to working environment in semiconductor packaging such as clean room environment, smock (attire), and roles & responsibility of process engineers. At the end of the course, students were given questions to test their understanding on the topics. Out of 53 students, 20 (38%) scored full marks. This shows the students had high interest of the subject matter and manage to learn the basic understanding of the topics presented.

Before end of the course, promotion slides including the benefits of joining IEEE EPS and upcoming IEMT conference were presented to the students. Overall, the short course met the objective and well received by the students judging from the online feedback given.

(Reported by: Azham Mohd Sukemi)
Young Professional Meeting with EPS BOG and Leaders at EPTC Conference, Singapore

The IEEE EPS Young Professional (YP) Meetup session proved to be a dynamic forum where emerging leaders and professionals in the field of electrical and electronics engineering converged to share insights, collaborate, and foster connections. This event, in conjunction with EPTC conference in Singapore provided a platform for young professionals to engage in meaningful discussions their possible career development with the EPS BoG and also respective leaders. Attendees had the opportunity to participate in interactive sessions and networking activities, enabling them to exchange ideas and build a supportive community. The meetup not only showcased the vibrant talent within the IEEE EPS community but also emphasized the importance of continuous learning and collaboration in shaping the future of the EPS landscape. Overall, the event served as an inspiring and enriching experience for young professionals looking to navigate and excel in their careers within the IEEE EPS network. Special thanks to all the EPS BoG and the leaders who joined the session. Also not forgetting Yan on preparing the beautiful flash cards for the YP to collect, which was indeed one of the highlights of the event too!

(Reported by: Yan Li & Dr Shaw Fong Wong)
IEMT 2024 Kickoff Meeting

IEMT 2024 Committee held our kickoff meeting on 01 December 2023 virtually. The meeting was attended by 24 committee members and chaired by the General chair. The agenda of the kickoff is listed below. The main purpose of the kick-off meeting was mainly to introduce all the committee members as well as to provide some quick updates to IEMT 2024. The date of the conference had been determined on 16-18 Oct 2024, held at G Hotel Gurney, Penang. Subsequently, various sub-committee lead, or representative provide a quick update into their own area. The meeting adjourned at 12noon.

(Reported by: Bernard Lim)

Best Engineering Student Award – University of Tunku Abdul Rahman Malaysia (UTAR) (con’t)

Titled “Development of an Instrumented Bed Monitoring System”, Mercedes Chan’s award-winning research was supervised by LKC FES academics Mr Chong Yu Zheng and Dr Chan Siow Cheng. It focused on reducing the burden of front-line healthcare workers by developing an instrumented bed monitoring system, which provides real-time monitoring of patient’s movement on the bed. The system features a sensor array located between the mattress and bed sheet to enable effective body movement and posture detection. Not to mention, it also features an alarm system and call function, which not only effectively improves the quality of healthcare, but also shortens the time interval of medical response between the healthcare workers and patients.

“In its current state, my project is greatly influenced by my grandmother’s extended hospitalisation. It provided me with a first-hand understanding of the challenges faced by individuals immobilised for long periods, which eventually led me to the expansion of the project scope to address the critical issue of bed sores, along with the function of a bed exit alarm,” said Mercedes Chan about her project.

(Reported by: Dr Ir Wong Yew Hoong)
IEEE-EPS Vice Chair Conferred Anugerah Tokoh Muda Kejuruteraan (The National Young Engineering Icon Award) 2023 by the Prime Minister of Malaysia!

It was an extreme honour that our EPS Vice Chair, Assoc. Prof. Ir. Dr. Wong Yew Hoong for being conferred with the prestigious award — Anugerah Tokoh Muda Kejuruteraan Negara (National Young Engineering Icon Award) 2023 by the Prime Minister of Malaysia, Dato' Seri Anwar Ibrahim on the 5th of December 2023. The awards ceremony successfully took place during the Hari Profesion Teknikal Negara (HPTN) 2023 at Dewan Damar Sari 1, Preccint 1, Putrajaya.

This is an utmost prestigious award for an engineer, particularly, a Young Engineer (below 40 years old), as this award is conferred to only one eligible winner annually. Malaysia, through the Board of Engineers Malaysia (BEM), established this award to acknowledge and recognize Malaysian Engineer who has made utmost significant contributions to the engineering fraternity at both the national and international levels. Moreover, this prestigious award is to recognize prominent young Malaysian engineer who upholds high integrity, has demonstrated remarkable leadership, and contributed immensely to the community. With all the above credentials attained, Ir. Dr. Wong Yew Hoong has also demonstrated creativity, innovativeness and resourcefulness in his roles, responsibilities, and functions by actively engaging in various learned societies such as IEEE-EPS, IEM, IMechE, and YSN-ASM, in various capacities.

Another recent highlight – Ir. Dr. Wong Yew Hoong was also the recipient of the most notable award in his field of expertise, i.e., 2020 EPS Outstanding Young Engineer Award from IEEE-EPS, USA for his contributions to the field of electronic packaging materials and semiconductor fabrication technologies through novel material and process development. Ir. Dr. Wong Yew Hoong is appreciative of the strong support given by IEEE–EPS Malaysia.

Assoc. Prof. Ir. Dr. Wong Yew Hoong is indeed the role model of the engineering profession and iconic figures in the engineering industry!

(Reported by: Dr Ir Wong Yew Hoong)
IEEE EPS Region 10 Program Director Prof Andrew Tay has invited all EPS Region 10 Chapter Chairs to attend a meeting on Dec 7, 1.30 - 3pm at the Grand Copthorne Waterfront Hotel, Singapore, in conjunction with EPTC 2023. IEEE EPS President Dr Kitty Pearsall and some members of the EPS BoG attended as well, including Bill Chen, Denise Manning who is IEEE EPS Executive Director and Toni Mattila who is IEEE EPS Chapter Development Director.

At the meeting, many Chapter Chairs presented a brief report of their Chapter’s activities throughout 2023 and what they have planned in the future. Team also discussed issues or matters related to EPS. It was a hybrid meeting, with some attended physically and some online.

Dr Eu Poh Leng who is the Senior Director of Package Innovation in NXP and the Chairlady of IEEE EPS Malaysia 2023 has presented details of activities organized or supported by IEEE EPS Malaysia Chapter which are more than 20 events, and key plan for 2024 which is the 40th IEMT Conference in Penang Malaysia, expecting to attract at least 500 participants.

Dr Eu also presented a report from IEEE EPS Vietnam on behalf of the Chairman Mr Mike Fadreguilan who is not able to make it. The formation of Vietnam Chapter in 2nd Half of 2023 is also a successful partnership between EPS Malaysia and EPS Vietnam. Committee members from EPS Malaysia including Wong Shaw Fong, Dr YY Tan, and Secretary Lim Sze Pei also attended.

It was a good meeting including sharing of secrets of success by each Chapter Chair that is very beneficial. Meeting ended with a Thank You note by Prof Andrew Tay and a group photo.

(Reported by: Dr Eu Poh Leng)
Best Engineering Student Award – University of Tunku Abdul Rahman Malaysia (UTAR)

Bachelor of Biomedical Engineering with Honours student Mercedes Chan Simh Peh from Lee Kong Chian Faculty of Engineering and Science (LKC FES) recently received the Best Engineering Student Award (BESA) 2023, awarded by IEEE Electronics Packaging Society (EPS), Malaysian Chapter. For her passionate contribution to the field of biomedical engineering, she received a cash prize of RM3,000 and a certificate.

BESA is an annual award introduced by IEEE EPS, Malaysian Chapter on 2017. It is catered for undergraduate students in Malaysia, aiming to reward and encourage technical excellence in Malaysia’s next generation of engineers. UTAR students or alumni have been the recipients of BESA every year since 2019, marking a significant milestone for both recipients and UTAR.

Excited to receive the award, Mercedes Chan enthused, “I would like to express my heartfelt gratitude as I am truly honoured to have received this prestigious award and recognition. This award is a testament not only to my individual efforts, but also to the collaborative efforts of my family, professors, and mentors who have guided and supported me. I am grateful for the opportunities that have led me to this point and, at the same time, excited about the future possibilities that lie ahead.”
The Sci-Tech 8.0 program unfolded on October 29, 2023, at the International Islamic University Malaysia (IIUM), captivating the minds of 40 enthusiastic children aged 7-12 from low-income families. IEEE Instrumentation & Measurement Society Malaysia Chapter has co-sponsored this program, along with other collaborators, Adab Youth Garage, Persatuan Penduduk Kampung Baru HICOM (PERWACOM), and Persatuan Penduduk PPR Gombak Setia.

This one-day event, orchestrated by IIUM Flagship 3.0 SCITECH, centered around three dynamic modules—Explorace, Makers Exhibition, and Robotic session (Microbit)—dedicated to fostering STEM (Science, Technology, Engineering, and Mathematics) fields. 40 dedicated IIUM students from Usrah In Action Sect 12 and 15 facilitated the immersive experience, guiding children through hands-on activities that translated theoretical STEM principles into practical applications.

The Explorace segment immersed children in interactive challenges, promoting problem-solving and teamwork. The Makers Exhibition showcased cutting-edge technologies like ROBOCON robots, 3D printers, and laser engravers, sparking curiosity and innovation among young minds. Furthermore, the Microbit sessions introduced coding and programming in robotics, empowering participants with fundamental technical skills.
Amphibious Electric Vehicle Competition

The Amphibious Electric Vehicle Competition 2023 took place on October 14, 2023, in conjunction with the Carnival STEAM UNLIMITED at SK Peramu Jaya, Pekan District Level 2023. This competition offers students an opportunity to learn by means of a friendly competition against their peers where students take responsibility for the design, construction, and performance of a mini electric-powered amphibious vehicle that will complete a race in the shortest possible time. Using any other materials, competitors will design and build a mini electric-powered amphibious vehicle that will race on a 10-meter racecourse. The winner of the competition will be the team whose vehicle is the top finisher in a series of head to head elimination rounds.

On October 2-3, 2023, the 13th National Technical Seminar on Unmanned System Technology (NUSYS 2023) took place at the USM Engineering Campus in Nibong Tebal, Pulau Pinang. The event was organized by IEEE OES Malaysia Chapter in collaboration with the organizer, Universiti Sains Malaysia (USM). The NUSYS 2023 seminar served as convergence point for leading scientists, researchers, engineers, scholars, and students from various corner of globe, fostering an environment for the exchange of knowledge and ideas within the field of unmanned system technology.

The conference featured four distinguished keynote speakers who shared their insights and expertise, contributing to the intellectual discourse and advancements in the domain. The engaging talks covered a spectrum of topics relevant to unmanned systems, providing attendees with valuable perspectives and cutting-edge developments. Notably, the conference attracted a diverse audience of approximately 60 participants, with some joining the event virtually through an online platform. This inclusive approach enabled the seamless integration of attendees, regardless of their geographical location, promoting a global exchange of information and collaboration.
On October 31 – November 3, 2023, a group of distinguished academics and researchers from the OES Malaysia Chapter and Northwestern Polytechnical University (NPU) recently came together for an enriching fourday event at Northwestern Polytechnical University in Xi’an, China. The delegation included prominent figures such as Professor Dr. Mohd Rizal Arshad from OES Malaysia Chapter team, Professor Dr. Guang Pan and Professor Dr. Huiping Li from NPU, among other esteemed guests. The program commenced with a comprehensive Joint Tech Seminar, followed by an exploration of the historical treasures of Xi’an.

Day 1: Joint Tech Seminar
The event began on 31 October 2023 with the Joint Tech Seminar. Starting at 9:00 AM, the seminar featured a series of insightful presentations from both OES Malaysia Chapter and NPU teams. These presentations covered diverse topics, from breakthroughs in technology to collaborative research achievements and insights into future tech trends. The morning session was rich in intellectual discourse, fostering a spirit of learning and collaboration. After the lunch break, the afternoon was dedicated to discussion sessions, providing practical insights into various technological fields. This provided a unique opportunity for hands-on learning and potential research collaborations. The day concluded with an interactive Q&A session, enabling a lively discussion and concluding remarks from the organizer.

The evening was reserved for a networking dinner, where participants engaged in informal discussions, shared ideas, and built professional connections.

Day 2: Tour of Xi’an
The final day of the event was a cultural tour of Xi’an. The morning began with a visit to the legendary Terracotta Army, offering attendees a peek into China’s rich historical heritage. The visit was both enlightening and inspiring, showcasing the artistic and cultural achievements of ancient China. In the afternoon, after a delightful lunch at a local restaurant, the group toured the Ancient City Wall and the Big Wild Goose Pagoda. These sites are not only significant for their historical and cultural value but also stand as testaments to the seamless blend of ancient traditions and modern developments characteristic of Xi’an. The day concluded with participants having the option to extend their stay, allowing further exploration of this vibrant city. This event was more than just an academic conference; it was an immersion into culture, blending the exploration of technological advancements with the appreciation of historical and cultural heritage. The participants left with enhanced knowledge, potential collaborative prospects, and a deeper understanding of Xi’an's rich cultural backdrop.
Representing IEEE OES Malaysia, "Science and Technology for the Preservation of Coral Reefs in Malaysia" was one of the talks at MRS 2023 event organized by the CSIR-National Institute of Oceanography (NIO), Goa, India, from 20-25 November 2023. This international symposium convened a diverse assembly of approximately 100 participants consisting of postgraduate students and academics, spanning countries such as Spain, India, Portugal, USA, and Norway, offering a vibrant platform for the exchange of insights and expertise on coral reef preservation.

The event’s dynamic agenda included technical sharing sessions, concise pitches, and immersive field demonstrations, collectively illuminating innovative solutions and fostering collaborative dialogues among global stakeholders. The varied geographical representation underscored a collective dedication to tackling the multifaceted challenges confronting coral reefs, transcending international borders to create a unified front for marine conservation.

The lessons learned and experiences gained during MRS 2023 will undoubtedly guide IEEE OES Malaysia towards effective contributions in the ongoing global pursuit of preserving and protecting our invaluable coral reefs.
CENCON 2023

The 2023 IEEE Conference on Energy Conversion (CENCON 2023) was held at Merdeka Palace Hotel and Suites, Kuching, Sarawak, on 23rd-24th October 2023. The conference's objective is to share the latest research in power electronics, electrical drives, renewable energy, modelling and control systems, and, at the same time, discover Malaysia, particularly Sarawak.

CENCON 2023 is organised and sponsored by the IEEE Power Electronics (PEL) Malaysia Chapter, co-organised by Power Electronics and Drives Research Group (PEDG), Universiti Teknologi Malaysia, and Department of Electrical Engineering, Universiti Malaysia Sarawak (UNIMAS) and technical co-sponsored by The Korean Institute of Power Electronics (KIPE).

(Reported by: Norjulia Mohamad Nordin)

Distinguished Lecturer Program By Prof Dr Kai Sun

On 24th October 2023, 3pm to 4pm, Prof Dr Kai Sun from Department of Electrical Engineering, Tsinghua University, China, delivered his distinguished lecture with title Advanced Bi-directional DC-DC Converter in Battery Energy Storage System. This lecture was delivered in a hybrid mode at Bangunan Fakulti Kejuruteraan, Universiti Malaysia Sarawak (UNIMAS). This lecture was attended by a 4th year student and lecturer from electrical engineering field.

(Reported by: Norjulia Mohamad Nordin)
A Technical Seminar titled “Multiswitch DC-DC Converter Topology for Single-phase Electric Vehicle Charger with High Power Density Consideration” was held on November 7th, 2023. This seminar was jointly organized by KSR Institute for Engineering and Technology India, Universiti Tun Hussein Onn Malaysia (UTHM), and IEEE PELS Chapter Malaysia. The technical seminar was themed and was presented by Associate Professor Asmarashid Ponniran from UTHM, whose expertise lies in power electronics.

The seminar took place at the KSR Institute for Engineering and Technology India in a face-to-face mode, with a total of 83 participants from India and Malaysia in attendance.

(Reported by: Asmarashid Ponniran and Norjulia Mohamad Nordin)
A workshop on Finite Element for Electromagnetic by Dr Azri Hizami was held in UMPSA, Kuantan, Pahang, on 8th November 2023. This workshop provided introduction to Finite Element simulation in Electromagnetism and also problem definition as well as a boundary condition of electromagnetism.

(Reported by: Azri Hizami and Norjulia Mohamad Nordin)

An industrial visit to TT Electronics, Kuantan was held on 27th October 2023. All participants including lecturers, undergraduate students and postgraduate students were exposed to the automation of Bobin and winding assembly. Participants also been exposed on the best practice in handling bobin and winding as well as common problem occurs.

(Reported by: Azri Hizami and Norjulia Mohamad Nordin)

A field trip to PETRONAS Refinery and Petrochemical Corporation Sdn Bhd Pengerang Johor, was hel on 9th November 2023. During this visits, all participants are exposed to practical insights into power electronics product manufacturing, transformers, power generators and testing processes.

(Reported by: Ramani Kannan and Norjulia Mohamad Nordin)
Technical Talk: A Novel Non-isolated High-gain DC-DC Converter Topology And Its Applications

A technical talk with titled A Novel Non-isolated High-gain DC-DC Converter Topology And Its Applications delivered by Ir. Dr Nor Zaihar Yahaya was held on 8th December 2023 at UTP. This talk exposed the participants on the development of a unique DC-DC converter design that offers high gain without the need for electrical isolation. DC-DC converters are devices that transform one voltage level to another, and the term "non-isolated" suggests that there might not be a galvanic barrier between the input and output.

(Reported by: Ramani Kannan and Norjulia Mohamad Nordin)
The School of Engineering, UOW Malaysia University College hosted its 3rd Engineering Undergraduate Research Symposium (EUReS) on 29th November 2023 with a theme “Nourishing Sustainable Futures: Bridging the Gap”. It is a signature event of the School of Engineering. It was conceived to showcase and demonstrate undergraduate students’ innovative ideas and creative projects that pivot on providing a sustainable solution. The event commenced with two keynote presentations by Ms. Michelle Woon, Nestlé Products Sdn. Bhd., and Dr. Marcella Papini, Women’s Research Engineers Network (WREN) co-founder. The event was followed by an assessment session of research presentation and prototype demonstration supported by a pool of distinguished external evaluators from industry and academia.

A professional talk on crafting cohesive dissertation titles: Aligning aim, problem statement and objectives for academic achievements was organized by the IET Malaysia chapter, UOW Malaysia, UCSI IEEE Student Chapter and IEEE RAS MALAYSIA. The guest speaker, Dr. Mastaneh Mokayef, has set the foundation for a focused and coherent research study. During her presentation, Dr. Mokayef emphasized the need to clearly define the aim of the dissertation, which reflects the overarching goal or purpose of the research. Aligning the aim with the title ensures a strong connection between the research focus and the title.

In the engineering professional world creating a good network to build a strong career is a must. It is important for those enrolled in this subject to know the value of a professional society and gain knowledge- how to enroll and get maximum benefit out of it. Dr. Mohamed Khan briefed the audience of more than 20 students and Engineering staffs the vision, mission and the complete IEEE organization structure and its benefits and how to open up a student branch.
ICIP 2023

The IEEE International Conference on Image Processing (ICIP) is the world’s largest conference focused on image and video processing and computer vision. The 30th edition of ICIP in 2023 was hosted by IEEE SPS Malaysia at the KL Convention Centre (KLCC) on October 7th to 11th, 2023. The conference boasted over 1000 participants and showcased world-class plenary speakers from EPFL, Google, and NASA, tutorials, exhibits, special sessions, industry sessions with over 20 global companies, and side events for women, students and young professionals as well as social events that greatly fosters collaboration, innovation and entrepreneurship.

The ICIP 2023 website is https://2023.ieeeicip.org/, while more photos and videos of the event can be found at the SPS Malaysia Facebook page.

STEM Workshops For Schools

IEEE SPS Malaysia organized two workshops to promote STEM for schools on November 2nd, 2023. One was on 3D Design and Printing, co-hosted by the CSII FG at Makerspace UTHM Johor, and assisted by 30 undergraduate students from FKEE UTHM. Participants comprised 30 students and 5 teachers from several schools in the area. Participants printed their name tags using a 3D printer, and then participated in a design competition where they were all given souvenirs to take home.

Meanwhile, Prof Hezerul Abdul Karim gave a talk on 5G, IoT and smart farming to 50 students and teachers at SMK Sri Permaisuri. This was followed by a hands-on workshop on IoT and Smart Farming given by MMU undergraduate students.

(Reported by: Mohd Norzali Hj Mohd & Hezerul Abdul Karim)
Congratulations to the Winners of the UPM FYP Exhibition 2023

We are delighted to announce that Aiman Fatina Muhamad Kamal has been selected as the recipient of the UTHM FYP Industry Award on July 5, 2023. Her project titled, “Develop a Prototype of an IoT Water Surface Garbage Cleaning Robot using a PV Panel” represents an outstanding achievement in the field. Warmest congratulations to the supervisor, Dr. Jabbar Al-Fattah Yahya, for providing exceptional guidance throughout the project. This recognition is a testament to their dedication and commitment to advancing the field of robotics system.

Congratulations to the recipients of the IEEE Final Year Project Award, Nik Muhammad Farhan bin Owi Siong Kiat @ Rustam Al and Sharifah Sakinah binti Syed Abdul Hamid, for IEEE SMC Malaysia Chapter 2023, in conjunction of FYP Exhibition in Universiti Putra Malaysia (UPM) and IEEE SMC Award ceremony on July 17, 2023. Their project titles were “Smart Monitoring for Wi-Fi based Fall Detection System” and “Convolutional Neural Network based Method for Assessment of Ergonomic Risk Factor.” Kudos also to the supervisors, Madam Siti Mariam binti Shafie and Madam Roslizah binti Ali, for their exceptional support and supervision.

Supporting ICoICT 2023 by MMU

Our chapter is proud to be the Technical Co-Sponsor for the 11th International Conference on Information and Communication Technology (ICoICT 2023) on August 23-24, 2023. A total of 114 papers, with 54.3% acceptance rate, were accepted and presented at this virtual conference, hosted by Multimedia University, Melaka. The papers were published and included into IEEE Xplore on September 29, 2023.

Supporting CIS-RAM 2023 by XMU

Our chapter is proud to be the Technical Co-Sponsor for the 10th IEEE International Conferences on Cybernetics and Intelligent Systems (CIS) and Robotics, Automation and Mechatronics (RAM), held in Penang on June 9-12, 2023. This conference is hosted by Xiamen Malaysia University (XMU).
The IEEE RFID Council Malaysia Chapter in collaboration with The UTAR and University of Nottingham Malaysia organised technical talk webinar on “Phishing-resistance Security with Passwordless Authentication using FIDO” on 9 November 2023. The number of attendance was 13 IEEE members and 83 non-IEEE attendees. The speaker was Mr. Sea Chong Seak, CTO of Signing Cloud Signing Cloud Sdn. Bhd. The objective of the event was to give exposure to the participants on the working principles of FIDO and the benefits of using FIDO over conventional authentication methods using password. FIDO is a passwordless authentication based on asymmetric cryptography that attempts to reduce the importance of passwords.

(Reported by: Daniel Pu Chuan Hsian)

A technical webinar entitled "Antenna Design for IoT and 5G Application" was held on 21 November 2023, at 10 am. The number of attendance was 27 IEEE members and 83 non-IEEE attendees. The speaker was Dr. Low Jen Hahn, Assistant Professor from UTAR. The webinar was conducted via Microsoft Team. This event was organized together with UTAR IEEE Student Chapter and IET Nottingham Student Chapter. The talk aimed to introduce and explore in the role of antennas in the future IoT and 5G application as well as provide insights to participants about the fundamental of antenna design. Dr. Low Jen Hahn had delivered a fruitful sharing session to the participants to have clearer idea in future outlook and opportunities in the antenna field.

(Reported by: Chee Pei Song)
The IEEE RFID Council Malaysia Chapter has co-organized a technical talk entitled “High Quality Paper Writing – Persuasive Writing with Evidence” with IEEE Malaysia ComSoc/VTS Joint Chapter and UTAR LKCFES on 8 December 2023. The number of attendance was 3 IEEE members and 18 non-IEEE attendees. Prof. Shui Yu is a Professor of School of Computer Science, University of Technology Sydney, Australia. His research interest includes Cybersecurity, Network Science, Big Data, and Mathematical Modelling. Prof. Yu promoted the research field of networking for big data since 2013, and his research outputs have been widely adopted by industrial systems, such as Amazon cloud security. He is currently serving the editorial boards of IEEE Communications Surveys and Tutorials (Area Editor) and IEEE Internet of Things Journal (Editor). He served as a Distinguished Lecturer of IEEE Communications Society (2018-2021). He is a Distinguished Visitor of IEEE Computer Society, and an elected member of Board of Governors of IEEE VTS and IEEE ComSoc, respectively. He is a member of ACM and AAAS, and a Fellow of IEEE. As high-quality publication is an important metric to most of us as a research fellow, many passionate young researchers struggle to find the right way to achieve their success in publication. In this talk, Prof. Shui Yu shared with the audience on his experience on how to write a high-quality paper and get accepted by high standard publisher. He also shares on how to increase the likelihood of getting the submitted paper being accepted by the reviewer. The talk provides a great insight to all the audience.
The International STEM & Innovation Colloquia Series (ISICS) Series-13 was successfully hosted by Universiti Malaysia Perlis (UniMAP) in collaboration with the IEEE Sensors & Nanotechnology Councils Malaysia (SNCM) and Kedah State Education Department (JPN Kedah). The event took place on the 14th of November 2023, from 9:00 am to 11:00 am (Malaysia Time). The event was conducted online through the Zoom platform and was also live-streamed on YouTube. The distinguished speaker for ISICS Series-13 was Alicia Dwyer Ciancioolo, the Senior Technical Lead for Advanced Entry, Descent and Landing Vehicle Technology Development at NASA Langley Research Center, Virginia, USA. Alicia Dwyer Ciancioolo possesses over two decades of experience in Mars exploration. She has played crucial roles in missions such as the Odyssey and Reconnaissance Orbiter aerobraking operations. Notably, she contributed significantly to the successful landings of the Curiosity Rover in 2012 and the InSight lander in 2018. Currently, Alicia serves as the Systems Engineering Team Deputy for the Artemis Program’s Human Landing System, contributing to lunar and Martian exploration. In her presentation entitled Journey to the Moon with Artemis, Alicia provided an insightful overview of the first Artemis missions, emphasizing how and why this return to the Moon will differ significantly from the historic Apollo program. The event saw a turnout of 180 attendees, including 40 IEEE members.

(Reported by: Hasnizah Aris)
The International Symposium on Emerging Trends in Semiconductor Technology (MiCSETS 2023) was successfully held online on the 29th of November 2023. The symposium was organized by the Center of Excellence in Micro System Technology (MiCTEC) in collaboration with the Faculty of Electronic Engineering, Institute of Nano Electronic Engineering (INEE), IEEE Sensors & Nanotechnology Council Malaysia, and IEEE Electronics Packaging Society. The symposium served as a platform for researchers, industries, academicians, scholars, professionals, and key players in related fields to come together and share their findings. The event was designed to facilitate networking and collaboration, providing a valuable opportunity for participants to engage in discussions on the emerging trends in semiconductor technology. A keynote speaker and 7 invited speakers from academics and industries have shared their expertise during the event. 83 attendees have attended the event.

(Reported by: Hasnizah Aris)
The International STEM & Innovation Colloquium Series (ISICS) Series-14 was proudly hosted by Universiti Malaysia Perlis (UniMAP) in collaboration with the IEEE Sensors & Nanotechnology Councils Malaysia (SNCM) and UniMAP Sport Engineering Research Centre. This event was organized on December 13, 2023 (Wednesday), from 9:00 am to 11:00 am (Malaysia Time). The platform for the event was online, utilizing both Zoom and YouTube Live Streaming. This program featured Prof. Rory A. Cooper who is currently a distinguished Professor, Assistant Vice Chancellor for Research for STEM-Health Sciences Collaborations, and Founding Director of Human Engineering Research Laboratories (HERL), School of Health & Rehabilitation Sciences, University of Pittsburgh, USA. He delivered his talk entitled "Forging a New Future: Participatory Action Design & Engineering Technologies with People with Disabilities". The talk emphasized collaborative efforts with disabled communities to co-create innovative solutions that address their unique needs and aspirations. Prof. Cooper shared insights into the challenges and opportunities inherent in this participatory approach, shedding light on its pivotal role in advancing social justice and inclusion. The event saw a turnout of 90 attendees, including 30 IEEE members.

(Reported by: Hasnizah Ari)
On December 7, 2023, from 8:30 AM to 1:30 PM, a significant event was conducted to promote Science, Technology, Engineering, and Mathematics (STEM) awareness among school students. Co-organized by the IEEE Sensors and Nanotechnology Council in collaboration with the Science, Technology & Innovation (STI) Awareness and Cultivation Program 2023 at S.K. Felda Chuping, Perlis, this initiative aimed to instill a passion for STEM disciplines among the younger generation. The IEEE Sensors and Nanotechnology Council played a pivotal role as a co-organizer, leveraging its expertise and resources to facilitate engaging STEM activities for school students. Collaborating with the STEM EduAction team of FKTEN, UniMAP, IEEE Malaysia Section, and dedicated school teachers, the team significantly contributed to the success of the event. The event received invaluable support from the Ministry of Science, Technology & Innovation (MOSTI) through the Science, Technology & Innovation (STI) Awareness and Cultivation Program 2023. This support played a crucial role in organizing and executing STEM-centric activities, fostering scientific curiosity and innovation among the students. Around 100 students participated in the event with 10 IEEE members participating as volunteers.

(Reported by: Hasnizah Aris)
This workshop was led by Kamil Hassan on behalf of our student branch in National Fintech Expo 2023. It took place as an engaging and enlightening session focused on the realms of AI and web development. It mainly revolved around the creation of an innovative web application capable of engaging in conversations with documents or PDFs. To demonstrate this, OpenAI API and Python were being utilized to develop a RAG (Retrieval-Augmented Generation) application. This application showcased the potential for using AI to interact with documents, offering a glimpse into its promising role in software development.

The annual SYWL Congress, open to all IEEE members, was a prestigious occasion hosted this year at Asia Pacific University, marking a momentous honor for our institution. The event commenced with a seamless registration process, paving the way for Dr. Nordin’s gracious opening remarks, which set an engaging and optimistic tone. Bernard then took the stage to highlight the SYWL activities in Malaysia, showcasing the remarkable achievements and ongoing initiatives. Following by that was Prof Saifur Rahman’s distinguished lecture on IEEE Perspectives related to SYWL, and IEEE Malaysia Section Dinner, providing a convivial atmosphere conducive to networking among the attendees.

A captivating Culture Show further enriched the event, celebrating diverse traditions. The networking session continued, fostering connections and idea exchanges until the event concluded at 10:00 PM.
The Industry Visit to Drone Academy Asia, conducted on November 8, 2023, marked an insightful exploration into the ever-evolving domain of drone technology. The event began with a thorough safety briefing and a captivating presentation by Drone Academy Asia experts, shedding light on cutting-edge advancements and industry practices. While hands-on experiences were limited due to operational constraints handled solely by the company’s skilled staff during the site tour, they offered a close-up view of operational setups, allowing attendees to witness practical applications firsthand. The engaging Q&A session facilitated robust discussions, enabling an exchange of ideas between students and industry professionals about career pathways and technological innovations.

2023 21st IEEE SCOReD was held at Asia Pacific University in December which lasted for two days. It provides a platform for local and international researchers, engineers and scientists from academia and industry to present and discuss the latest technological advances and research progress in the fields of computing, technology, engineering and other related areas.
The IEEE Students Congress 2023, held successfully on 5th Nov 2023, was a dynamic event attended by 40 students. The event commenced with an inspiring opening speech by Prof. Madya Ir. Dr. Norhana Arsat, the Club Counselor of IEEE UKM SB. The students then delved into the program, which featured a series of enlightening sessions. The program included student congress videos, offering insights into the world of IEEE and its student branches. Two impactful career talks were delivered. "Career Aspirations: Nothing is Impossible!" was presented by Dr. Eu Poh Leng, Senior Director from NXP Semiconductors, and "Navigating Success: Industry Engagement & Insights for Young Professionals" was delivered by Mr. Wong Shaw Fong, Engineering Manager at Intel Corporation. Their talks offered valuable career guidance. In addition, David Chong Teak Wei, Head of AI department at Ever AI Technologies, shared insights in a talk titled "Why Machine Learning?" shedding light on this trending field. The event also featured IEEE Student Branches Networking Videos from IEEE UKM SB, IEEE UM SB, IEEE UiTM SB, and IEEE UNITEN SB. The IEEE Students Congress 2023 concluded with a closing remark by Dr. Nordin Ramli, Chair of IEEE Malaysia Section. It was an engaging and informative event, fostering learning, networking, and career development opportunities for the attending students.

(Reported by: Chee Yik Hui)
From 25th October 2023 to 15th November 2023, the IEEE Universiti Malaya Student Branch (UMSB) had successfully organized Mini Automatic Solar Tracker Design Challenge 2.0, which was held at the Faculty of Engineering, Universiti Malaya. The event was also co-organized by IEEE Dielectrics and Electrical Insulation Society (DEIS) Malaysia Chapter. The event was fully funded and supported by IEEE Malaysia Section through the Student Activity Fund 2023. The event was launched by the Counselor of IEEE UMSB, Associate Professor Ir. Dr. Hazlee Azil Illias from the Department of Electrical Engineering, Faculty of Engineering, Universiti Malaya.

In this activity, participants were required to build a prototype of mini automatic solar tracker that is smart, low cost and efficient from 25th October 2023 to 15th November 2023. They were given free time to construct the prototype. The prototype was able to track the sunlight movement to harvest possible maximum energy. Eight groups of participants, which consists of up to 3 members in every group, participated in this program.

On 15th November 2023, all participations demonstrated their prototype in front of the judges and visitors who came to the demonstration day of the prototype. Visitors took the opportunity to visit the demonstration day and were amazed with the prototype demonstrated by the participants. The prototype was assessed based on its functionality and tidiness. The soft skills were assessed based on the critical thinking, teamwork, leadership and communication skills. Also, on the same day, membership drive of IEEE UMSB was conducted by the committee members at the same time. The purposes of the membership drive were to introduce IEEE and IEEE UMSB to the students, to attract new IEEE members and to widen the networking between the committee members and students. Some students had expressed their interest to be an IEEE Student Member.
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2024 IEEE Conference on Biomedical Engineering and Sciences IECBES2024. Year 2024 marks the Malaysia chapter's 12th year of commitment to recognizing and featuring research fronts in biomedical engineering and sciences in its flagship conference. It is with this pride and honor that we invite you to attend IECBES2024, which will be held in Penang, Malaysia on December 11-13, 2024. In our efforts to ensure ease of accessibility and the sharing of research findings to all relevant stakeholders, we are committed to making IECBES2024 a hybrid conference.

As the premier biomedical engineering and sciences conference in this region, we have carefully established strategic partnerships with key authorities and figures in the field to share cutting-edge research and innovation to facilitate and push boundaries in biomedical engineering and sciences research. The conference has come a long way since its inception in 2010.

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